

ZL50016 Enhanced 1 K Digital Switch

Data Sheet

May 2013

Features

- 1024 channel x 1024 channel non-blocking digital Time Division Multiplex (TDM) switch at 4.096 Mbps, 8.192 Mbps and 16.384 Mbps or using a combination of ports running at 2.048 Mbps, 4.096 Mbps, 8.192 Mbps, and 16.384 Mbps
- 16 serial TDM input, 16 serial TDM output streams
- Output streams can be configured as bidirectional for connection to backplanes
- Exceptional input clock cycle to cycle variation tolerance (20 ns for all rates)
- Per-stream input and output data rate conversion selection at 2.048 Mbps, 4.096 Mbps, 8.192 Mbps, or 16.384 Mbps. Input and output data rates can differ
- Per-stream high impedance control outputs (STOHZ) for 8 output streams
- Per-stream input bit delay with flexible sampling point selection

Ordering Information

ZL50016GAG2 256 Ball PBGA* Trays, Bake & Drypack

*Pb Free Tin/Silver/Copper -40°C to +85°C

- Per-stream output bit and fractional bit advancement
- Per-channel ITU-T G.711 PCM A-Law/μ-Law Translation
- Input clock: 4.096 MHz, 8.192 MHz, 16.384 MHz
- Input frame pulses:61 ns, 122 ns, 244 ns
- Four frame pulse and four reference clock outputs
- Three programmable delayed frame pulse outputs
- Per-channel constant or variable throughput delay for frame integrity and low latency applications
- Per Stream (16) Bit Error Rate Test circuits complying to ITU-O.151

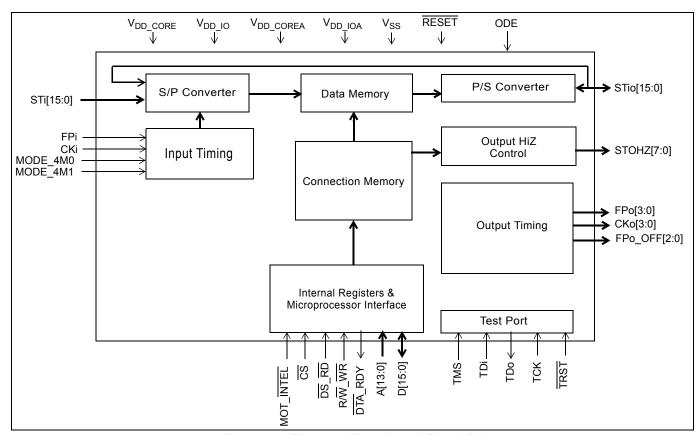


Figure 1 - ZL50016 Functional Block Diagram



Data Sheet

- Per-channel high impedance output control
- Per-channel message mode

Microsemi 🧼

- Control interface compatible with Intel and Motorola 16-bit non-multiplexed buses
- Connection memory block programming
- Supports ST-BUS and GCI-Bus standards for input and output timing
- IEEE-1149.1 (JTAG) test port
- 3.3 V I/O with 5 V tolerant inputs; 1.8 V core voltage

Applications

- PBX and IP-PBX
- Small and medium digital switching platforms
- Remote access servers and concentrators
- Wireless base stations and controllers
- Multi service access platforms
- **Digital Loop Carriers**
- Computer Telephony Integration

Description

The ZL50016 is a maximum 1024 x 1024 channel non-blocking digital Time Division Multiplex (TDM) switch. It has sixteen input streams (STi0 - 15) and sixteen output streams (STio0 - 15). The device can switch 64 kbps and Nx64 kbps TDM channels from any input stream to any output stream. Each of the input and output streams can be independently programmed to operate at any of the following data rates: 2.048 Mbps, 4.096 Mbps, 8.192 Mbps, or 16.384 Mbps. The ZL50016 provides up to eight high impedance control outputs (STOHZ0 - 7) to support the use of external tristate drivers for the first eight output streams (STio0 - 15). The output streams can be configured to operate in bi-directional mode, in which case STi0 - 15 will be ignored.

The device contains two types of internal memory - data memory and connection memory. There are four modes of operation - Connection mode, Message mode, BER mode, and high impedance mode. In Connection Mode, the contents of the connection memory define, for each output stream and channel, the source stream and channel (the actual data to be output is stored in the data memory). In Message Mode, the connection memory is used for the storage of microprocessor data. Using Microsemi's Message Mode capability, microprocessor data can be broadcast to the data output streams on a per-channel basis. This feature is useful for transferring control and status information for external circuits or other TDM devices. In BER mode the output channel data is replaced with a pseudorandom bit sequence (PRBS) from one of 16 PRBS generators that generates a 2¹⁵-1 pattern. On the input side channels can be routed to one of 16 bit error detectors. In high impedance mode the selected output channel can be put into a high impedance state.

The configurable non-multiplexed microprocessor port allows users to program various device operating modes and switching configurations. Users can employ the microprocessor port to perform register read/write, connection memory read/write, and data memory read operations. The port is configurable to interface with either Motorola or Intel-type microprocessors.

The device also supports the mandatory requirements of the IEEE-1149.1 (JTAG) standard via the test port.



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Changes Summary

The following table captures changes from November 2006 issue to May 2013 issue.

Page	Item	Change
Multiple	Zarlink logo and name reference	Updated to Microsemi [®] logo and name.
1	"Ordering Information"	Removed the following part numbers: ZL50016GAC 256 Ball PBGA Trays ZL50016QCC 256 Lead LQFP Trays ZL50015QCG1 256 Lead LQFP* Trays, Bake & Drypack

The following table captures the changes from January 2006 to November 2006.

Page	ltem	Change			
1	"Ordering Information"	Updated Ordering Information.			

The following table captures the changes from October 2004 to January 2006.

Page	Item	Change
13	Pin Description "CKi"	Clarified pin description for CKi.
31	11.3, "Output Clock Frequencies"	 Added new section to describe output clock frequencies.





Pinout Diagrams 1.0

BGA Pinout 1.1

\	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	
Α	V _{SS}	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	V _{SS}	Α
В	NC	STi10	STi5	STi4	CKo2	STi0	CKo0	NC	V _{DD} _ COREA	FPi	CKi	IC_Open	IC_Open	IC_GND	ODE	NC	В
С	NC	STi9	V _{SS}	STi7	STi6	STi1	CKo1	NC	V _{SS}	IC_Open	IC_Open	IC_Open	IC_GND	V _{SS}	STio15	NC	С
D	NC	STi11	V _{DD_IO}	STi3	STi2	NC	NC	NC	NC	V _{SS}	FPo_ OFF1	IC_GND	STio13	V _{DD_IO}	STio14	NC	D
Е	NC	STi14	STi8	V _{DD_IO}	V _{SS}	V _{DD} _ CORE	NC	NC	NC	NC	V _{DD} _ CORE	V _{SS}	V _{DD_IO}	STio12	FPo2	NC	E
F	NC	STi15	STi12	STi13	V _{DD_IO}	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	V _{DD_IO}	IC_Open	FPo3	FPo_ OFF2	NC	F
G	NC	RESET	IC_GND	IC_Open	TDo	V _{DD_IO}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DD_IO}	A12	A13	FPo1	FPo0	NC	G
Н	NC	V _{SS}	V _{SS}	V _{DD} _ COREA	NC	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	A7	A9	A10	FPo_ OFF0	A11	NC	Н
J	NC	V _{DD_IOA}	V _{DD_IOA}	V _{SS}	V _{SS}	CKo3	V _{SS}	V _{SS}	V _{SS}	V _{SS}	A3	A4	A5	A8	A6	NC	J
K	NC	V _{SS}	TMS	V _{SS}	V _{DD} _ COREA	V _{DD_IO}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DD_IO}	IC_Open	A0	A2	A1	NC	К
L	NC	V _{DD} _ COREA	TRST	TCK	V _{DD_IO}	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	V _{DD_IO}	STio10	STio11	STio9	NC	L
М	NC	NC	TDi	D0	V _{SS}	V _{DD} _ CORE	V _{DD} _ CORE	D6	D10	V _{DD} _ CORE	V _{DD} _ CORE	V _{SS}	MOT_ INTEL	MODE_ 4M0	STio8	NC	М
N	NC	NC	V _{DD_IO}	STio0	STOHZ3	D1	D5	D7	D11	D13	R <u>/W</u> _WR	DTA_ RDY	STio4	V _{DD_IO}	STOHZ5	NC	N
Р	NC	NC	V _{SS}	STio1	STio3	STOHZ1	D3	D8	D14	NC	STio5	STOHZ4	STOHZ6	V _{SS}	STOHZ7	NC	Р
R	NC	NC	STOHZ0	STio2	STOHZ2	D2	D4	D9	D12	D15	CS	DS_RD	MODE_ 4M1	STio6	STio7	NC	R
Т	V_{SS}	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	V _{SS}	Т
,	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	_

Note: A1 corner identified by metallized marking. **Note:** Pinout is shown as viewed through top of package.

Figure 2 - ZL50016 256-Ball 17 mm x 17 mm PBGA (as viewed through top of package)



1.2 QFP Pinout

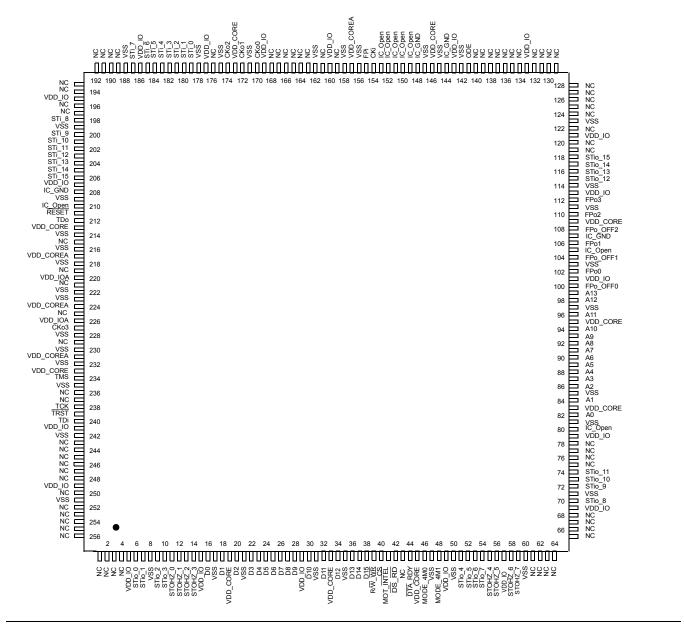


Figure 3 - ZL50016 256-Lead 28 mm x 28 mm LQFP (top view)





2.0 Pin Description

PBGA Pin Number	LQFP Pin Number	Pin Name	Description
E6, E11, F6, F7, F10, F11, L6, L7, L10, L11, M6, M7, M10, M11	19, 33, 45, 83, 95, 109, 146, 173, 213, 233	V _{DD_CORE}	Power Supply for the core logic: +1.8 V
H4, K5, B9, L2	217, 231, 157, 224	V _{DD_COREA}	Power Supply for analog circuitry: +1.8 V
D3, D14, E4, E13, F5, F12, G6, G11, K6, K11, L5, L12, N3, N14	5, 15, 29, 49, 57, 69, 79, 101, 113, 121, 133, 143, 160, 169, 177, 186, 195, 207, 241, 249	V _{DD_IO}	Power Supply for I/O: +3.3 V
J2, J3	220, 226	V_{DD_IOA}	Power Supply for the CKo5 and CKo3 outputs: +3.3 V
A1, A16, C3, C9, C14, D10, E5, E12, F8, F9, G7, G8, G9, G10, H2, H3, H6, H7, H8, H9, H10, J4, J5, J7, J8, J9, J10, K2, K4, K7, K8, K9, K10, L8, L9, M5, M12, P3, P14, T1, T16	8, 17, 21, 31, 35, 47, 50, 60, 71, 81, 85, 97, 103, 111, 114, 123, 142, 145, 147, 156, 158, 162, 171, 175, 178, 188, 199, 209, 214, 216, 218, 222, 223, 228, 230, 232, 235, 242, 251	V _{SS}	Ground



PBGA Pin Number	LQFP Pin Number	Pin Name	Description
К3	234	TMS	Test Mode Select (5 V-Tolerant Input with Internal Pull-up) JTAG signal that controls the state transitions of the TAP controller. This pin is pulled high by an internal pull-up resistor when it is not driven.
L4	238	TCK	Test Clock (5 V-Tolerant Schmitt-Triggered Input with Internal Pull-up) Provides the clock to the JTAG test logic.
L3	239	TRST	Test Reset (5 V-Tolerant Input with Internal Pull-up) Asynchronously initializes the JTAG TAP controller by putting it in the Test-Logic-Reset state. This pin should be pulsed low during power-up to ensure that the device is in the normal functional mode. When JTAG is not being used, this pin should be pulled low during normal operation.
М3	240	TDi	Test Serial Data In (5 V-Tolerant Input with Internal Pull-up) JTAG serial test instructions and data are shifted in on this pin. This pin is pulled high by an internal pull-up resistor when it is not driven.
G5	212	TDo	Test Serial Data Out (5 V-Tolerant Three-state Output) JTAG serial data is output on this pin on the falling edge of TCK. This pin is held in high impedance state when JTAG is not enabled.
B12, B13, C10, C11, F13, G4, K12, C12,	80, 105, 150, 151, 152, 153, 210, 149	IC_Open	Internal Test Mode (5 V-Tolerant Input with Internal Pull-down) These pins may be left unconnected.
G3, D12, B14, C13	144, 107, 148, 208	IC_GND	Internal Test Mode Enable (5 V-Tolerant Input) These pins MUST be low.





PBGA Pin Number	LQFP Pin Number	Pin Name	Description
A8, A9, A14,	61, 62,	NC	No Connect
A15, E10,	63, 64,		These pins MUST be left unconnected.
M2, N2, P2,	65, 66,		
P16, R2,	67, 68,		
R16, T6, T7,	134, 135,		
T8, T9, T10,	136, 137,		
T11, T12,	138, 139,		
T13, T14,	140, 215,		
T15, D16,	219, 225,		
E16, C16,	229, 236,		
B16, A13,	237, 125,		
A12, A10,	126, 127,		
A11, N1,	128, 129,		
M1, P1, R1,	130, 131,		
T2, T3, T5,	132, 253,		
T4, N16,	254, 255,		
M16, L16,	256, 1, 2,		
K16, H16,	3, 4, 75,		
J16, G16,	76, 77,		
F16,D9, E8,	78, 119,		
C8, E7, D6,	120, 122,		
H5, P10, E1,	124,159,		
D1, G1, F1,	163, 165,		
J1, H1, K1,	167, 176,		
L1, A7, A5,	221, 43,		
A6, A4, A3,	243, 244,		
A2, C1, B1,	245, 246,		
E9, D8, B8,	247, 248,		
D7	250, 252,		
	189, 190,		
	191, 192,		
	193, 194,		
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	161, 164,		
	166, 168		
M14, R13	46, 48	MODE_4M0, MODE_4M1	4M Input Clock Mode 0 to 1 (5 V-Tolerant Input with internal pull-down) These two pins should be tied together and are typically used to select CKi = 4.096 MHz operation. See Table 7, "ZL50016 Operating Modes" on page 31 for a detailed explanation. See Table 13, "Control Register (CR) Bits" on page 38 for CKi and FPi selection using the CKIN1 - 0 bits.



PBGA Pin Number	LQFP Pin Number	Pin Name	Description
G15, G14, E15, F14	102, 106, 110, 112	FPo0 - 3	ST-BUS/GCI-Bus Frame Pulse Outputs 0 to 3 (5 V-Tolerant Three-state Outputs) FPo0: 8 kHz frame pulse corresponding to the 4.096 MHz output clock of CKo0. FPo1: 8 kHz frame pulse corresponding to the 8.192 MHz output clock of CKo1. FPo2: 8 kHz frame pulse corresponding to 16.384 MHz output clock of CKo2. FPo3: Programmable 8 kHz frame pulse corresponding to 4.096 MHz, 8.192 MHz, 16.384 MHz, or 32.768 MHz output clock of CKo3.
H14, D11, F15	100, 104, 108	FPo_OFF0 - 2	Generated Offset Frame Pulse Outputs 0 to 2 (5 V-Tolerant Three-state Outputs) Individually programmable 8 kHz frame pulses, offset from the output frame boundary by a programmable number of channels.
B7, C7, B5, J6	170, 172, 174, 227	CKo0 - 3	ST-BUS/GCI-Bus Clock Outputs 0 to 3 (5 V-Tolerant Three-state Outputs) CKo0: 4.096 MHz output clock. CKo1: 8.192 MHz output clock. CKo2: 16.384 MHz output clock. CKo3: 4.096 MHz, 8.192 MHz or 16.384 MHz programmable output clock. 32.768MHz if in multiplied clock mode.
B10	155	FPi	ST-BUS/GCI-Bus Frame Pulse Input (5 V-Tolerant Schmitt-Triggered Input) This pin accepts the frame pulse which stays active for 61 ns, 122 ns or 244 ns at the frame boundary. The frame pulse frequency is 8 kHz. The frame pulse associated with the CKi must be applied to this pin. If the data rate is 16.384 Mbps, a 61 ns wide frame pulse must be used. By default, the device accepts a negative frame pulse in ST-BUS format, but it can accept a positive frame pulse instead if the FPINP bit is set high in the Control Register (CR). It can accept a GCI-formatted frame pulse by programming the FPINPOS bit in the Control Register (CR) to high.
B11	154	CKi	ST-BUS/GCI-Bus Clock Input (5 V-Tolerant Schmitt-Triggered Input) This pin accepts a 4.096 MHz, 8.192 MHz or 16.384 MHz clock. In divided clock mode the clock frequency applied to this pin must be twice the highest input or output data rate. In multiplied clock mode the clock frequency applied to this pin must be twice the highest input data rate. The exception is, when data is running at 16.384 Mbps, a 16.384 MHz clock must be used. By default, the clock falling edge defines the input frame boundary, but the device allows the clock rising edge to define the frame boundary by programming the CKINP bit in the Control Register (CR).



PBGA Pin Number	LQFP Pin Number	Pin Name	Description
B6, C6, D5, D4, B4, B3, C5, C4, E3, C2, B2, D2, F3, F4, E2, F2	179, 180, 181, 182, 183, 184, 185, 187, 198, 200, 201, 202, 203, 204, 205, 206,	STi0 - 15	Serial Input Streams 0 to 15 (5 V-Tolerant Inputs with Internal Pull-downs) The data rate of each input stream can be selected independently using the Stream Input Control Registers (SICR[n]). In the 2.048 Mbps mode, these pins accept serial TDM data streams at 2.048 Mbps with 32 channels per frame. In the 4.096 Mbps mode, these pins accept serial TDM data streams at 4.096 Mbps with 64 channels per frame. In the 8.192 Mbps mode, these pins accept serial TDM data streams at 8.192 Mbps with 128 channels per frame. In the 16.384 Mbps mode, these pins accept TDM data streams at 16.384 Mbps with 256 channels per frame.
N4, P4, R4, P5, N13, P11, R14, R15, M15, L15, L13, L14, E14, D13, D15, C15	6, 7, 9, 10, 51, 52, 53, 54, 70, 72, 73, 74, 115, 116, 117, 118	STio 0 - 15	Serial Output Streams 0 to 15 (5 V-Tolerant Slew-Rate-Limited Three-state I/Os with Enabled Internal Pull-downs) The data rate of each output stream can be selected independently using the Stream Output Control Registers (SOCR[n]). In the 2.048 Mbps mode, these pins output serial TDM data streams at 2.048 Mbps with 32 channels per frame. In the 4.096 Mbps mode, these pins output serial TDM data streams at 4.096 Mbps with 64 channels per frame. In the 8.192 Mbps mode, these pins output serial TDM data streams at 8.192 Mbps with 128 channels per frame. In the 16.384 Mbps mode, these pins output serial TDM data streams at 16.384 Mbps with 256 channels per frame. These output streams can be used as bi-directionals by programming BDL (bit 6) of Internal Mode Selection (IMS) register.
R3, P6, R5, N5, P12, N15, P13, P15	11, 12, 13, 14, 55, 56, 58, 59	STOHZ 0 - 7	Serial Output Streams High Impedance Control 0 to 7 (5 V-Tolerant Slew-Rate-Limited Three-state Outputs) These pins are used to enable (or disable) external three-state buffers. When an output channel is in the high impedance state, the STOHZ drives high for the duration of the corresponding output channel. When the STio channel is active, the STOHZ drives low for the duration of the corresponding output channel. STOHZ outputs are available for STio0 - 7 only.
B15	141	ODE	Output Drive Enable (5 V-Tolerant Input with Internal Pull-up) This is the output enable control for STio0 - 15 and the output-driven-high control for STOHZ0 - 7. When it is high, STio0 - 15 and STOHZ0 - 7 are enabled. When it is low, STio0 - 15 are tristated and STOHZ0 - 7 are driven high.
M4, N6, R6, P7, R7, N7, M8, N8, P8, R8, M9, N9, R9, N10, P9, R10	16, 18, 20, 22, 23, 24, 25, 26, 27, 28, 30, 32, 34, 36, 37, 38	D0 - 15	Data Bus 0 to 15 (5 V-Tolerant Slew-Rate-Limited Three-state I/Os) These pins form the 16-bit data bus of the microprocessor port.



PBGA Pin Number	LQFP Pin Number	Pin Name	Description
N12	44	DTA_RDY	Data Transfer Acknowledgment_Ready (5 V-Tolerant Three-state Output) This active low output indicates that a data bus transfer is complete for the Motorola interface. For the Intel interface, it indicates a transfer is completed when this pin goes from low to high. An external pull-up resistor MUST hold this pin at HIGH level for the Motorola mode. An external pull-down resistor MUST hold this pin at LOW level for the Intel mode.
R11	40	ĊŚ	Chip Select (5 V-Tolerant Input) Active low input used by the Motorola or Intel microprocessor to enable the microprocessor port access.
N11	39	R/W_WR	Read/Write_Write (5 V-Tolerant Input) This input controls the direction of the data bus lines (D0 - 15) during a microprocessor access. For the Motorola interface, this pin is set high and low for the read and write access respectively. For the Intel interface, a write access is indicated when this pin goes low.
R12	42	DS_RD	Data Strobe_Read (5 V-Tolerant Input) This active low input works in conjunction with CS to enable the microprocessor port read and write operations for the Motorola interface. A read access is indicated when it goes low for the Intel interface.
K13, K15, K14, J11, J12, J13, J15, H11, J14, H12, H13, H15, G12, G13	82, 84, 86, 87, 88, 89, 90, 91, 92, 93, 94, 96, 98, 99	A0 - 13	Address 0 to 13 (5 V-Tolerant Inputs) These pins form the 14-bit address bus to the internal memories and registers.
M13	41	MOT_INTEL	Motorola_Intel (5 V-Tolerant Input with Internal Pull-up) This pin selects the Motorola or Intel microprocessor interface to be connected to the device. When this pin is unconnected or connected to high, Motorola interface is assumed. When this pin is connected to ground, Intel interface should be used.
G2	211	RESET	Device Reset (5 V-Tolerant Input with Internal Pull-up) This input (active LOW) puts the device in its reset state that disables the STio0 - 15 drivers and drives the STOHZ0 - 7 outputs to high. It also preloads registers with default values and clears all internal counters. To ensure proper reset action, the reset pin must be low for longer than 1 μs . Upon releasing the reset signal to the device, the first microprocessor access cannot take place for at least 600 μs due to the time required to stabilize the device from the power-down state. Refer to Section Section 13.2 on page 32 for details.



3.0 Device Overview

The device has sixteen ST-BUS/GCI-Bus inputs (STi0 - 15) and sixteen ST-BUS/GCI-Bus outputs (STio0 - 15). STio0 - 15 can also be configured as bi-directional pins, in which case STi0 - 15 will be ignored. It is a non-blocking digital switch with 1024 64 kbps channels and is capable of performing rate conversion between ST-BUS/GCI-Bus inputs and ST-BUS/GCI-Bus outputs. The ST-BUS/GCI-Bus inputs accept serial input data streams with data rates of 2.048 Mbps, 4.096 Mbps, 8.192 Mbps and 16.384 Mbps on a per-stream basis. The ST-BUS/GCI-Bus outputs deliver serial data streams with data rates of 2.048 Mbps, 4.096 Mbps, 8.192 Mbps and 16.384 Mbps on a per-stream basis. The device also provides eight high impedance control outputs (STOHZ0 - 7) to support the use of external ST-BUS/GCI-Bus tristate drivers for the first eight sixteen ST-BUS/GCI-Bus outputs (STio0 -7).

By using Microsemi's message mode capability, microprocessor data stored in the connection memory can be broadcast to the output streams on a per-channel basis. This feature is useful for transferring control and status information for external circuits or other ST-BUS/GCI-Bus devices.

The device uses the ST-BUS/GCI-Bus input frame pulse (FPi) and the ST-BUS/GCI-Bus input clock (CKi) to define the input frame boundary and timing for sampling the ST-BUS/GCI-Bus input streams with various data rates. The output data streams will be driven by and have their timing defined by FPi and CKi in Divided Clock mode (CLKM bit 11 Table 13, Control Register (CR) Bits. In Multiplied Clock mode, the output data streams will be driven by an internally generated clock, which is multiplied from CKi internally. In Multiplied Clock mode, the output data streams will be driven by an internally generated clock, which is multiplied from CKi internally. Refer to Application Note ZLAN-120 for further explanation of the different modes of operation.

There are two clock modes for this device:

The first is the Divided Clock mode. In this mode, output streams are clocked by input CKi. Therefore the output streams have exactly the same jitter as the input streams. The output data rate can be the same as or lower than the input data rate, but the output data rate cannot be higher than what CKi can drive. For example, if CKi is 4.096 MHz, the output data rate cannot be higher than 2.048 Mbps. The second clock mode is called Multiplied Clock mode. In this mode, CKi is used to generate a 16.384 MHz clock internally, and output streams are driven by this internal clock. In Multiplied Clock mode, the data rate of output streams can be any rate, but output jitter may not be exactly the same as input jitter.

A Motorola or Intel compatible non-multiplexed microprocessor port allows users to program the device to operate in various modes under different switching configurations. Users can use the microprocessor port to perform internal register and memory read and write operations. The microprocessor port has a 16-bit data bus, a 14-bit address bus and six control signals (MOT_INTEL, CS, DS_RD, R/W_WR and DTA_RDY).

The device supports the mandatory requirements of the IEEE-1149.1 (JTAG) standard via the test port.

4.0 Data Rates and Timing

The ZL50016 has 16 serial data inputs and 16 serial data outputs. Each stream can be individually programmed to operate at 2.048 Mbps, 4.096 Mbps, 8.192 Mbps or 16.384 Mbps. Depending on the data rate there will be 32 channels, 64 channels, 128 channels or 256 channels, respectively, during a 125 μs frame.

The output streams can be programmed to operate as bi-directional streams. By setting BDL (bit 6) in the Internal Mode Selection (IMS) register, the input streams 0 - 15 (STi0 - 15) are internally tied low, and the output streams 0 - 15 (STio0 - 15) are set to operate in a bi-directional mode. The input data rate is set on a per-stream basis by programming STIN[n]DR3 - 0 (bits 3 - 0) in the Stream Input Control Register 0 - 15 (SICR0 - 15). The output data rate is set on a per-stream basis by programming STO[n]DR3 - 0 (bits 3 - 0) in the Stream Output Control Register 0 - 15 (SOCR0 - 15). The output data rates do not have to match or follow the input data rates. The maximum number of channels switched is limited to 1024 channels. If all 16 input streams were operating at 16.384 Mbps (256 channels per stream), this would result in 4096 channels. Memory limitations prevent the device from operating at this capacity. A maximum capacity of 1024 channels will occur if four of the streams are operating at 16.384 Mbps, eight of the streams are operating at 8.192 Mbps or all streams operating at 4.096 Mbps. With all streams operating at 2.048 Mbps, the capacity will be reduced to 512 channels. However, as each stream can be



programmed to a different data rate, any combination of data rates can be achieved, as long as the total channel count does not exceed 1024 channels. It should be noted that only full stream can be programmed for use. The device does not allow fractional streams.

4.1 External High Impedance Control, STOHZ0 - 7

There are 16 external high impedance control signals, STOHZ0 - 7, that are used to control the external drivers for per-channel high impedance operations. Only the first eight ST-BUS/GCI-Bus (STio0 - 7) outputs are provided with corresponding STOHZ signals. The STOHZ outputs deliver the appropriate number of control timeslot channels based on the output stream data rate. Each control timeslot lasts for one channel time. When the ODE pin is high and the OSB (bit 2) of the Control Register (CR) is also high, STOHZ0 - 7 are enabled. When the ODE pin, OSB (bit 2) of the Control Register (CR) or the RESET pin is low, STOHZ0 - 7 are driven high, together with all the ST-BUS/GCI-Bus outputs being tristated. Under normal operation, the corresponding STOHZ outputs of any unused ST-BUS/GCI-Bus channel (high impedance) are driven high. Refer to Figure 16 on page 27 for a diagrammatical explanation.

4.2 Input Clock (CKi) and Input Frame Pulse (FPi) Timing

The frequency of the input clock (CKi) for the ZL50016 depends on the operation mode selected. In divided clock mode, CKi must be at least twice the highest input or output data rate. For example, if the highest input data rate is 4.096 Mbps and the highest output data rate is 8.192 Mbps, the input clock, CKi, must be 16.384 MHz, which is twice the highest overall data rate. The only exception to this is for 16.384 Mbps input or output data. In this case, the input clock, CKi, is equal to the data rate. The input frame pulse, FPi, must always follow CKi. In multiplied clock mode the frequency of CKi must be at least twice the highest input data rate regardless of the output data rate. An APLL is used to multiple CKi to generate an internal clock that is used to output clocks and STio streams. Following the example above, if the highest input data rate is 4.096 Mbps, the input clock, CKi, must be 8.192 MHz, regardless of the output data rate. The only exception to this is for 16.384 Mbps input or output data. In this case, the input clock, CKi, is equal to the data rate. The input frame pulse, FPi, must always follow CKi.

In either mode the user has to program the CKIN1 - 0 (bits 6 - 5) in the Control Register (CR) to indicate the width of the input frame pulse and the frequency of the input clock supplied to the device.

Highest <i>Input or Output</i> Data Rate	CKIN 1-0 Bits	Input Clock Rate (CKi)	Input Frame Pulse (FPi)
16.384 Mbps or 8.192 Mbps	00	16.384 MHz	8 kHz (61 ns wide pulse)
4.096 Mbps	01	8.192 MHz	8 kHz (122 ns wide pulse)
2.048 Mbps	10	4.096 MHz	8 kHz (244 ns wide pulse)

Table 1 - CKi and FPi Configurations for Divided Clock Modes



Microsemi

Data Sheet

Highest Input Data Rate	CKIN 1-0 Bits	Input Clock Rate (CKi)	Input Frame Pulse (FPi)
16.384 Mbps or 8.192 Mbps	00	16.384 MHz	8 kHz (61 ns wide pulse)
4.096 Mbps	01	8.192 MHz	8 kHz (122 ns wide pulse)
2.048 Mbps	10	4.096 MHz	8 kHz (244 ns wide pulse)

Table 2 - CKi and FPi Configurations for Multiplied Clock Mode

The ZL50016 accepts positive and negative ST-BUS/GCI-Bus input clock and input frame pulse formats via the programming of CKINP (bit 8) and FPINP (bit 7) in the Control Register (CR). By default, the device accepts the negative input clock format and ST-BUS format frame pulses. However, the switch can also accept a positive-going clock format by programming CKINP (bit 8) in the Control Register (CR). A GCI-Bus format frame pulse can be used by programming FPINPOS (bit 9) and FPINP (bit 7) in the Control Register (CR).

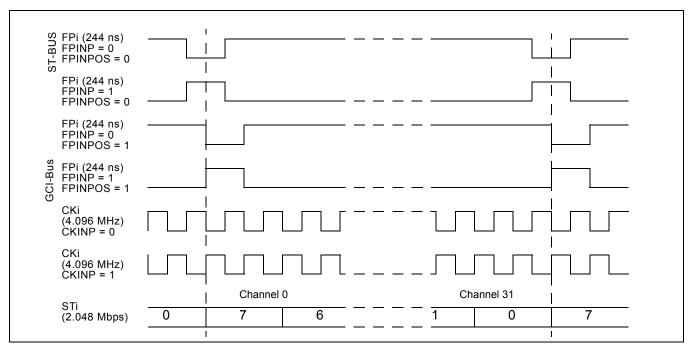


Figure 4 - Input Timing when CKIN1 - 0 bits = "10" in the CR



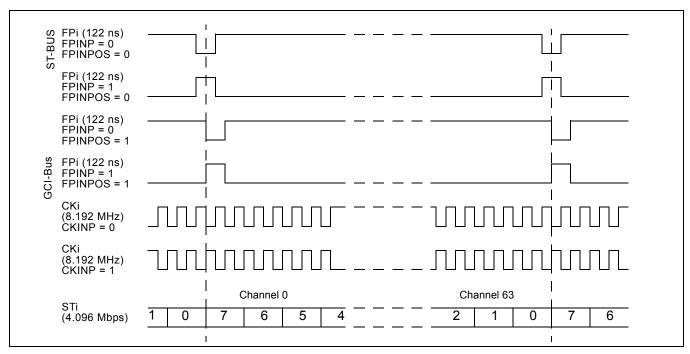


Figure 5 - Input Timing when CKIN1 - 0 bits = "01" in the CR

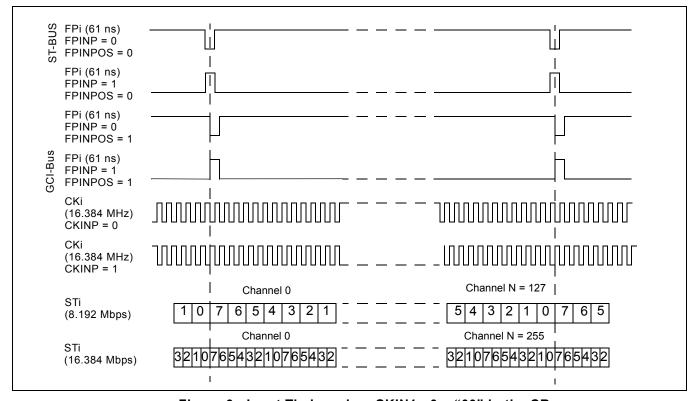


Figure 6 - Input Timing when CKIN1 - 0 = "00" in the CR



5.0 ST-BUS and GCI-Bus Timing

The ZL50016 is capable of operating using either the ST-BUS or GCI-Bus standards. The output timing that the device generates is defined by the bus standard. In the ST-BUS standard, the output frame boundary is defined by the falling edge of CKo while FPo is low. In the GCI-Bus standard, the frame boundary is defined by the rising edge of CKo while FPo goes high. The data rates define the number of channels that are available in a 125 μ s frame pulse period.

By default, the ZL50016 is configured for ST-BUS input and output timing. To set the input timing to conform to the GCI-Bus standard, FPINPOS (bit 9) and FPINP (bit 7) in the Control Register (CR) must be set. To set output timing to conform to the GCI-Bus standard, FPO[n]P and FPO[n]POS must be set in the Output Clock and Frame Pulse Selection Register (OCFSR). The CKO[n]P bits in the Output Clock and Frame Pulse Selection Register control the polarity (positive-going or negative-going) of the output clocks.

6.0 Output Timing Generation

The ZL50016 generates frame pulse and clock timing. There are four output frame pulse pins (FPo0 - 3) and four output clock pins (CKo0 - 3). All output frame pulses are 8 kHz output signals. By default, the output frame boundary is defined by the falling edge of the CKo0, while FPo0 is low. At the output frame boundary, the CKo1, CKo2 and CKo3 output clocks will by default have a falling edge, while FPo1, FPo2 and FPo3 will be low. The duration of the frame pulse low cycle and the frequency of the corresponding output clock are shown in Table 3 on page 20. Every frame pulse and clock output can be tristated by programming the enable bits in the Internal Mode Selection (IMS) register.

Pin Name	Output Timing Rate	Output Timing Unit	
FPo0 pulse width	244	ns	
CKo0	4.096	MHz	
FPo1 pulse width	122	ns	
CKo1	8.192	MHz	
FPo2 pulse width	61	ns	
CKo2	16.384	MHz	
FPo3 pulse width	244, 122, 61 or 30	ns	
CKo3 4.096, 8.192, 16.384 or 32.768		MHz	

Table 3 - Output Timing Generation

The output timing is dependent on the operation mode that is selected. When the device is in Divided Clock mode, the frequencies on CKo0 - 3 cannot be greater than the input clock, CKi. For example, if the input clock is 8.192 MHz, the CKo2 pin will not produce a valid output clock and the CKo3 pin can only be programmed to output a 4.096 MHz or 8.192 MHz clock signal.

The device also delivers positive or negative output frame pulse and ST-BUS/GCI-Bus output clock formats via the programming of various bits in the Output Clock and Frame Pulse Selection Register (OCFSR). By default, the device delivers the negative output clock format. The ZL50016 can also deliver GCI-Bus format output frame pulses by programming bits of the Output Clock and Frame Pulse Selection Register (OCFSR). As there is a separate bit setting for each frame pulse output, some of the outputs can be set to operate in ST-BUS mode and others in GCI-Bus mode.

The following figures describe the usage of the FPO0P, FPO1P, FPO2P, FPO3P, CKO0P, CKO1P, CKO2P and CKO3P bits to generate the FPo0 - 3 and CKo0 - 3 timing.

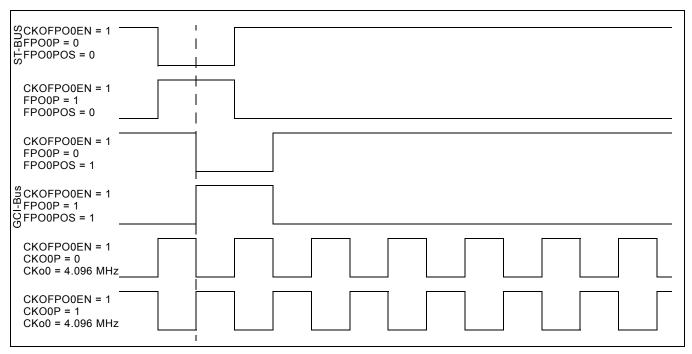


Figure 7 - Output Timing for CKo0 and FPo0

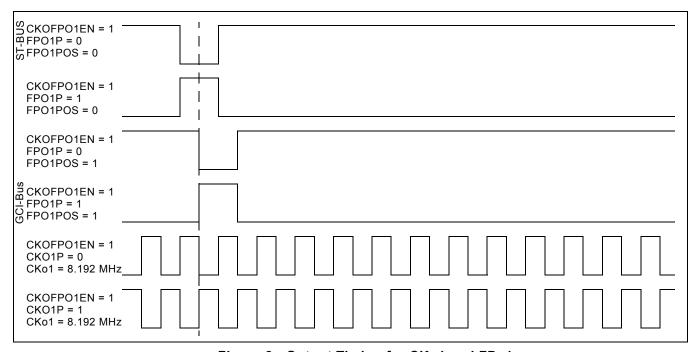
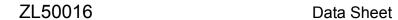


Figure 8 - Output Timing for CKo1 and FPo1





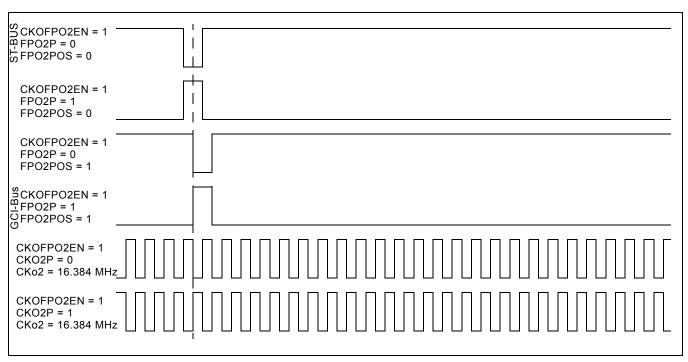


Figure 9 - Output Timing for CKo2 and FPo2

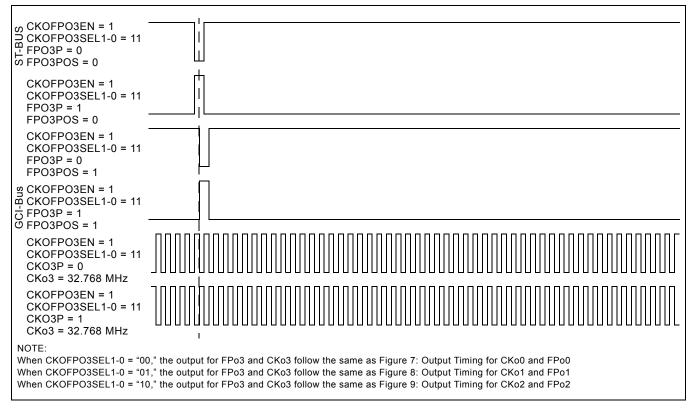


Figure 10 - Output Timing for CKo3 and FPo3 with CKoFPo3SEL1-0="11"



7.0 Data Input Delay and Data Output Advancement

Various registers are provided to adjust the input delay and output advancement for each input and output data stream. The input bit delay and output bit advancement can vary from 0 to 7 bits for each individual stream.

If input delay of less than a bit is desired, different sampling points can be used to handle the adjustments. The sampling point can vary from 1/4 to 4/4 with a 1/4-bit increment for all input streams, unless the stream is operating at 16.384 Mbps, in which case the fractional bit delay has a 1/2-bit increment. By default, the sampling point is set to the 3/4-bit location for non-16.384 Mbps data rates and the 1/2-bit location for the 16.384 Mbps data rate.

The fractional output bit advancement can vary from 0 to 3/4 bits, again with a 1/4-bit increment, unless the output stream is operating at 16.384 Mbps, in which case the output bit advancement has a 1/2-bit increment from 0 to 1/2 bit. By default, there is 0 output bit advancement.

Although input delay or output advancement features are available on streams which are operating in bi-directional mode it is not recommended, as it can easily cause bus contention. If users require this function special attention must be given to the timing to ensure contention is minimized.

7.1 Input Bit Delay Programming

The input bit delay programming feature provides users with the flexibility of handling different wire delays when designing with source streams for different devices.

By default, all input streams have zero bit delay, such that bit 7 is the first bit that appears after the input frame boundary (assuming ST-BUS formatting). The input delay is enabled by STIN[n]BD2-0 (bits 8 - 6) in the Stream Input Control Register 0 - 15 (SICR0 - 15) as described in Table 22 on page 48. The input bit delay can range from 0 to 7 bits.

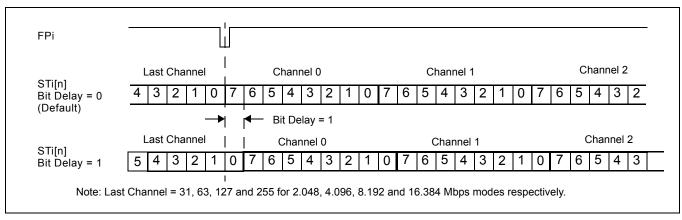


Figure 11 - Input Bit Delay Timing Diagram (ST-BUS)



Data Sheet

Input Bit Sampling Point Programming 7.2

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In addition to the input bit delay feature, the ZL50016 allows users to change the sampling point of the input bit by programming STIN[n]SMP 1-0 (bits 5 - 4) in the Stream Input Control Register 0 - 15 (SICR0 - 15). For input streams operating at any rate except 16.384 Mbps, the default sampling point is at 3/4 bit and users can change the sampling point to 1/4, 1/2, 3/4 or 4/4 bit position. When the stream is operating at 16.384 Mbps, the default sampling point is 1/2 bit and can be adjusted to a 4/4 bit position.

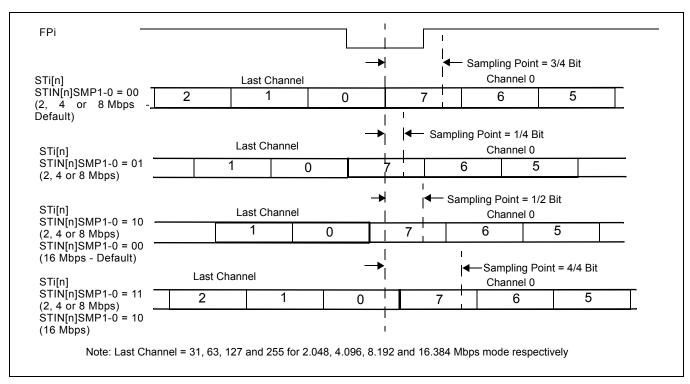


Figure 12 - Input Bit Sampling Point Programming



The input delay is controlled by STIN[n]BD2-0 (bits 8 - 6) to control the bit shift and STIN[n]SMP1 - 0 (bits 5 - 4) to control the sampling point in the Stream Input Control Register 0 - 15 (SICR0 - 15).

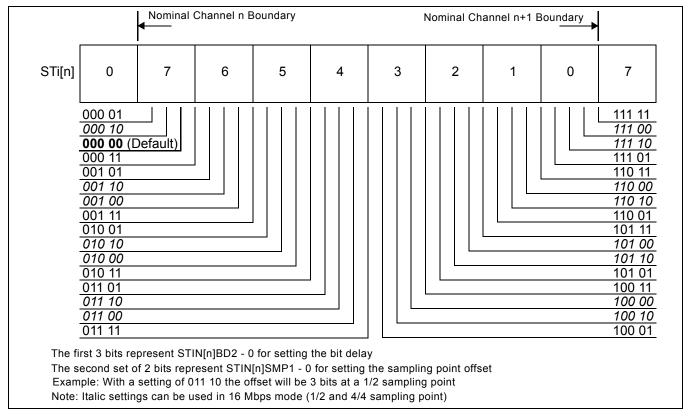


Figure 13 - Input Bit Delay and Factional Sampling Point

7.3 Output Advancement Programming

This feature is used to advance the output data of individual output streams with respect to the output frame boundary. Each output stream has its own bit advancement value which can be programmed in the Stream Output Control Register 0 - 15 (SOCR0 - 15).

By default, all output streams have zero bit advancement such that bit 7 is the first bit that appears after the output frame boundary (assuming ST-BUS formatting). The output advancement is enabled by STO[n]AD 2 - 0 (bits 6 - 4) of the Stream Output Control Register 0 - 15 (SOCR0 - 15) as described in Table 24 on page 51. The output bit advancement can vary from 0 to 7 bits.



Data Sheet

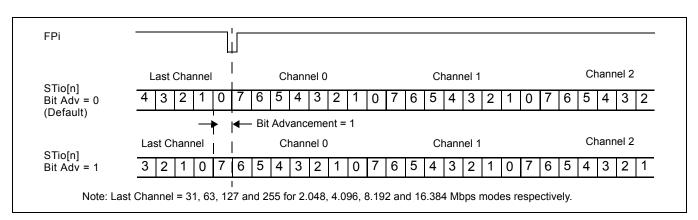


Figure 14 - Output Bit Advancement Timing Diagram (ST-BUS)

7.4 Fractional Output Bit Advancement Programming

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In addition to the output bit advancement, the device has a fractional output bit advancement feature that offers better resolution. The fractional output bit advancement is useful in compensating for varying parasitic load on the serial data output pins.

By default all of the streams have zero fractional bit advancement such that bit 7 is the first bit that appears after the output frame boundary. The fractional output bit advancement is enabled by STO[n]FA 1 - 0 (bits 8 - 7) in the Stream Output Control Register 0 - 15 (SOCR0 - 15). For all streams running at any data rate except 16.384 Mbps the fractional bit advancement can vary from 0, 1/4, 1/2 to 3/4 bits. For streams operating at 16.384 Mbps, the fractional bit advancement can be set to either 0 or 1/2 bit.

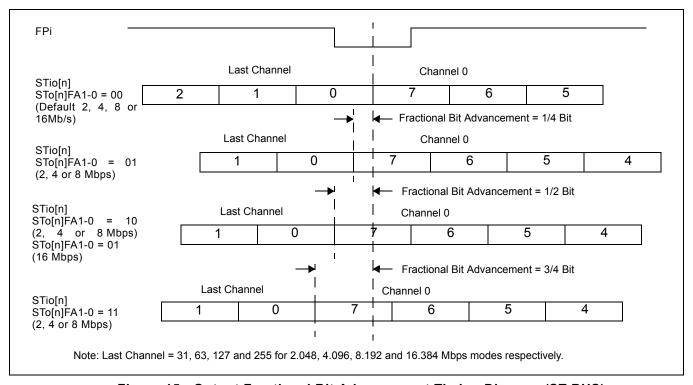


Figure 15 - Output Fractional Bit Advancement Timing Diagram (ST-BUS)



7.5 External High Impedance Control Advancement

The external high impedance signals can be programmed to better match the timing required by the external buffers. By default, the output timing of the STOHZ signals follows the programmed channel delay and bit offset of their corresponding ST-BUS/GCI-Bus output streams. In addition, for all high impedance streams operating at any data rate except 16.384 Mbps, the user can advance the STOHZ signals a further 0, 1/4, 1/2, 3/4 or 4/4 bits by programming STOHZ[n]A 2 - 0 (bit 11 - 9) in the Stream Output Control Register. When the stream is operating at 16.384 Mbps, the additional STOHZ advancement can be set to 0, 1/2 or 4/4 bits by programming the same register.

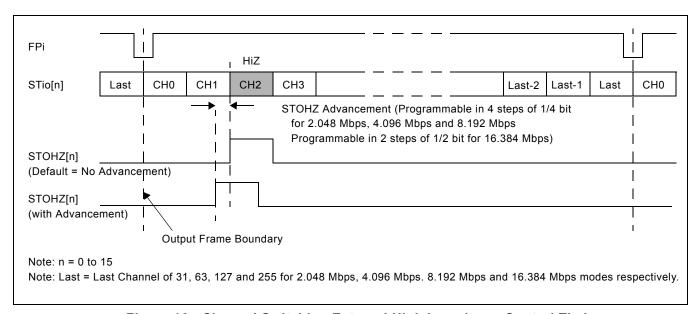


Figure 16 - Channel Switching External High Impedance Control Timing

8.0 Data Delay Through the Switching Paths

The switching of information from the input serial streams to the output serial streams results in a throughput delay. The device can be programmed to perform timeslot interchange functions with different throughput delay capabilities on a per-channel basis. For voice applications, select variable throughput delay to ensure minimum delay between input and output data. In wideband data applications, select constant delay to maintain the frame integrity of the information through the switch. The delay through the device varies according to the type of throughput delay selected by the V/\overline{C} (bit 14) in the Connection Memory Low when CMM = 0.

8.1 Variable Delay Mode

Variable delay mode causes the output channel to be transmitted as soon as possible. This is a useful mode for voice applications where the minimum throughput delay is more important than frame integrity. The delay through the switch can vary from 7 channels to 1 frame + 7 channels. To set the device into variable delay mode, VAREN (bit 4) in the Control Register (CR) must be set before V/\overline{C} (bit 14) in the Connection Memory Low when CMM = 0. If the VAREN bit is not set and the device is programmed for variable delay mode, the information read on the output stream will not be valid.

In variable delay mode, the delay depends on the combination of the source and destination channels of the input and output streams.



m = input channel number	n-m <= 0	0 < n-m < 7	r	n-m = 7	n-m > 7
n = output channel number			STio < STi	STio >= STi	
T = Delay between input and output	1 frame - (m-n)	1 frame	+ (n-m)	n-m	

Table 4 - Delay for Variable Delay Mode

For example, if Stream 4 Channel 2 is switched to Stream 5 Channel 9 with variable delay, the data will be output in the same 125 μ s frame. Contrarily, if Stream 6 Channel 1 is switched to Stream 9 Channel 3, the information will appear in the following frame.

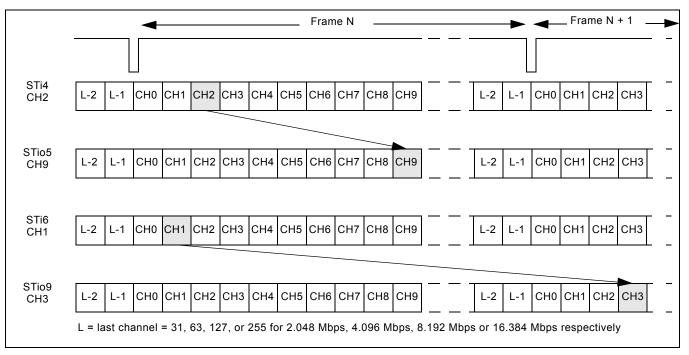


Figure 17 - Data Throughput Delay for Variable Delay

8.2 Constant Delay Mode

In this mode, frame integrity is maintained in all switching configurations. The delay though the switch is 2 frames - Input Channel + Output Channel. This can result in a minimum of 1 frame + 1 channel delay if the last channel on a stream is switched to the first channel of a stream. The maximum delay is 3 frames - 1 channel. This occurs when the first channel of a stream is switched to the last channel of a stream. The constant delay mode is available for all output channels.

The data throughput delay is expressed as a function of ST-BUS/GCI-Bus frames, input channel number (m) and output channel number (n). The data throughput delay (T) is:

$$T = 2 \text{ frames} + (n - m)$$

The constant delay mode is controlled by V/\overline{C} (bit 14) in the Connection Memory Low when CMM = 0. When this bit is set low, the channel is in constant delay mode. If VAREN (bit 4) in the Control Register (CR) is set (to enable variable throughput delay on a chip-wide basis), the device can still be programmed to operate in constant delay mode.

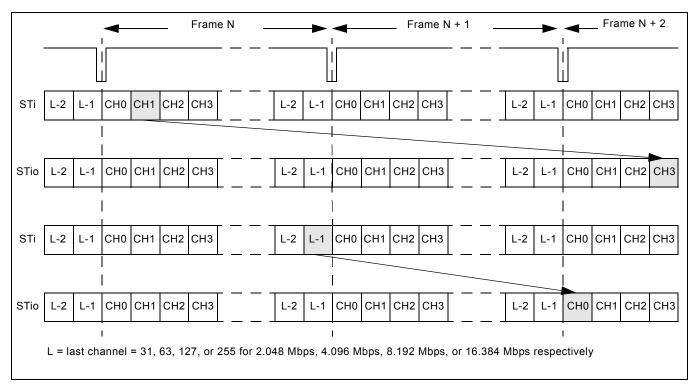


Figure 18 - Data Throughput Delay for Constant Delay

9.0 Connection Memory Description

The connection memory consists of two blocks, Connection Memory Low (CM_L) and Connection Memory High (CM_H). The CM_L is 16 bits wide and is used for channel switching and other special modes. The CM_H is 5 bits wide and is used for the voice coding function. When UAEN (bit 15) of the Connection Memory Low (CM_L) is low, μ -law/A-law conversion will be turned off and the contents of CM_H will be ignored. Each connection memory location of the CM_L or CM_H can be read or written via the 16 bit microprocessor port within one microprocessor access cycle. See Table 29 on page 54 for the address mapping of the connection memory. Any unused bits will be reset to zero on the 16-bit data bus.

For the normal channel switching operation, CMM (bit 0) of the Connection Memory Low (CM_L) is programmed low. SCA7 - 0 (bits 8 - 1) indicate the source (input) channel address and SSA4 - 0 (bits 13 - 9) indicate the source (input) stream address. The 5-bit contents of the CM_H will be ignored during the normal channel switching mode without the μ -law/A-law conversion when UAEN (bit 15) of the Connection Memory Low (CM_L) is set to zero. If μ -law/A-law conversion is required, the CM_H bits must be programmed first to provide the voice/data information, the input coding law and the output coding law before the assertion of UAEN (bit 15) in the Connection Memory Low.

When CMM (bit 0) of the Connection Memory Low (CM_L) is programmed high, the ZL50016 will operate in one of the special modes described in Table 31 on page 56. When the per-channel message mode is enabled, MSG7 - 0 (bit 10 - 3) in the Connection Memory Low (CM_L) will be output via the serial data stream as message output data. When the per-channel message mode is enabled, the μ -law/A-law conversion can also be enabled as required.



Data Sheet

10.0 **Connection Memory Block Programming**

This feature allows for fast initialization of the connection memory after power up.

Memory Block Programming Procedure

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- 1. Set MBPE (bit 3) in the Control Register (CR) from low to high.
- 2. Configure BPD2 0 (bits 3 1) in the Internal Mode Selection (IMS) register to the desired values to be loaded into CM_L.
- 3. Start the block programming by setting MBPS (bit 0) in the Internal Mode Selection Register (IMS) high. The values stored in BPD2 - 0 will be loaded into bits 2 - 0 of all CM L positions. The remaining CM L locations (bits 15 - 3) and the programmable values in the CM H (bits 4 - 0) will be loaded with zero values.

The following tables show the resulting values that are in the CM L and CM H connection memory locations.

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Value	0	0	0	0	0	0	0	0	0	0	0	0	0	BPD2	BPD1	BPD0

Table 5 - Connection Memory Low After Block Programming

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Value	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Table 6 - Connection Memory High After Block Programming

Note: Bits 15 to 5 are reserved in Connection Memory High and should always be 0.

It takes at least two frame periods (250 µs) to complete a block program cycle.

MBPS (bit 0) in the Control Register (CR) will automatically reset to a low position after the block programming process has completed.

MBPE (bit 3) in the Internal Mode Selection (IMS) register must be cleared from high to low to terminate the block programming process. This is not an automatic action taken by the device and must be performed manually.

Note: Once the block program has been initiated, it can be terminated at any time prior to completion by setting MBPS (bit 0) in the Control Register (CR) or MBPE (bit 3) in the Internal Mode Selection (IMS) register to low. If the MBPE bit was used to terminate the block programming, the MBPS bit will have to be set low before enabling other device operations.

11.0 **Device Operation in Divided Clock and Multiplied Clock Modes**

This device has two main operating modes - Divided Clock mode and Multiplied Clock mode.

In Multiplied Clock mode, output clocks and frame pulses are generated from an internal high-speed clock synchronized to CKi and FPi. Therefore, all specified output clock rates and data rates are available on CKo0-3 and STio0-31. In Divided Clock mode, output clocks and frame pulses are directly divided from CKi/FPi. Therefore, the output clock rate cannot exceed the CKi rate (the output data rates are also limited as per Table 1). The input data rate cannot exceed the CKi rate in either Multiplied or Divided Clock modes, because input data are always sampled directly by CKi.

Table 7, "ZL50016 Operating Modes" on page 31 summarizes the different modes of operation available within the ZL50016. Each Major mode (explained below) has various associated Minor modes that are determined by setting the MODE_4M Input Control pins and the OPM bit in the Control Register (Table 13, "Control Register (CR) Bits" on page 38) indicated in the table.

Devic	е	Input P	ins	CR Register	Output Clock	Pins	Data Pins		
Operating	Mode	Control	Signal	Bit	Reference Lock	Enabled	CI	ock Source	
Major	Minor	MODE_4M [1:0]	CKi	ОРМ	CKo0-3	CKo0-3	STi	STo	
Divided	4 M	11	4 M	0	CKi	Yes	CKi	CKo0-3	
Clock	8/16 M	00	8/16 M					(CKi)	
Multiplied	4 M	11	4 M	1	CKi MULT			CKo0-3	
Clock	8/16 M	00	8/16 M					(CKi MULT)	

Legend:

Reference Lock - Refers to what signal the output pins are locked to:

Table 7 - ZL50016 Operating Modes

11.1 Divided Clock Mode Operation

When the device is in Divided Clock mode, STio0 - 15 are driven by CKi. In this mode, the output streams and clocks have the same amount of jitter as the input clock (CKi), but the input and output data rate cannot exceed the input data rate defined by CKi. For example, if CKi is 4.096 MHz, the input and output data rate cannot be higher than 2.048 Mbps, and the generated output clock rates cannot exceed 4.096 MHz.

11.2 Multiplied Clock Mode Operation

When the device is in Multiplied Clock mode, device hardware is used to multiply CKi internally. STio0 - are driven by this internally generated clock. In this mode, the output clocks and data can run at any of the specified rates, but they may have different jitter characteristics from the input clock (CKi). The input data rates are still limited by the CKi rate (as per Table 1), as input data are always sampled directly by CKi.

11.3 Output Clock Frequencies

The device can generate a limited number of clock and frame pulse output signals. All signals are synchronous to each other and are locked to the input CKi and FPi. The device can provide outputs with the following frequencies, with the exception that when in Divided Clock mode, the output clock rate cannot exceed the input CKi rate.

CKo0	4.096 MHz
CKo1	8.192 MHz
CKo2	16.384 MHz
CKo3	4.096 MHz, 8.192 MHz, 16.384 MHz or 32.768 MHz
FPo0	8 kHz (244 ns wide pulse)
FPo1	8 kHz (122 ns wide pulse)
FPo2	8 kHz (61 ns wide pulse)
FPo3	8 kHz (244 ns, 122 ns, 61 ns or 30 ns wide pulse)

Table 8 - Generated Output Frequencies

X - Don't care or not applicable.

Cki = Bypass. Cki is passed directly through to CKo0-3.

Cki MULT = Cki is passed through clock multiplier to CKo0-3.

Clock Source - Refers to which clock samples STi and which clock outputs STo; STi applies when STi or STio is input; STo applies when STio is output.



12.0 Microprocessor Port

The device provides access to the internal registers, connection memories and data memories via the microprocessor port. The microprocessor port is capable of supporting both Motorola and Intel non-multiplexed microprocessors. The microprocessor port consists of a 16-bit parallel data bus (D15 - 0), 14 bit address bus (A13 - 0) and six control signals (MOT_INTEL, CS, DS_RD, R/W_WR and DTA_RDY).

The data memory can only be read from the microprocessor port. For a data memory read operation, D7 - 0 will be used and D15 - 8 will output zeros.

For a CM_L read or write operation, all bits (D15 - 0) of the data bus will be used. For a CM_H write operation, D4 - 0 of the data bus must be configured and D15 - 5 are ignored. D15 - 5 must be driven either high or low. For a CM_H read operation, D4 - 0 will be used and D15 - 5 will output zeros.

Refer to Figure 20 on page 60, Figure 21 on page 61, Figure 22 on page 62 and Figure 23 on page 63 for the microprocessor timing.

13.0 Device Reset and Initialization

The RESET pin is used to reset the ZL50016. When this pin is low, the following functions are performed:

- synchronously puts the microprocessor port in a reset state
- · tristates the STio0 15 outputs
- · drives the STOHZ0 7 outputs to high
- preloads all internal registers with their default values (refer to the individual registers for default values)
- clears all internal counters

13.1 Power-up Sequence

The recommended power-up sequence is for the V_{DD_IO} supply (normally +3.3 V) to be established before the power-up of the V_{DD_CORE} supply (normally +1.8 V). The V_{DD_CORE} supply may be powered up at the same time as V_{DD_IO} , but should not "lead" the V_{DD_IO} supply by more than 0.3 V.

13.2 Device Initialization on Reset

Upon power up, the ZL50016 should be initialized as follows:

- Set the ODE pin to low to disable the STio0 15 outputs and to drive STOHZ0 7 to high
- Set the TRST pin to low to disable the JTAG TAP controller
- Reset the device by pulsing the RESET pin to zero for longer than 1 μs
- After releasing the RESET pin from low to high, wait for a certain period of time (see Note below) for the
 device to stabilize from the power down state before the first microprocessor port access can occur
- Program CKIN1 0 (bit 6 -5) in the Control Register (CR) to define the frequency of the CKi and FPi inputs
- Wait at least 500 μs prior to the next microport access (see Note below)
- Use the block programming mode to initialize the connection memory
- Release the ODE pin from low to high after the connection memory is programmed

Note: If CKi is 16.384 MHz, the waiting time is 500 μ s; if CKi is 8.192 MHz, the waiting time is 1 ms; if CKi is 4.096 MHz, the waiting time is 2 ms.



13.3 Software Reset

In addition to the hardware reset from the \overline{RESET} pin, the device can also be reset by using software reset SRSTSW (bit 1) in the Software Reset Register (SRR).

14.0 Pseudo Random Bit Generation and Error Detection

The ZL50016 has one Bit Error Rate (BER) transmitter and one BER receiver for each pair of input and output streams, resulting in 16 transmitters connected to the output streams and 16 receivers associated with the input streams. Each transmitter can generate a BER sequence with a pattern of 2^{15} -1 pseudorandom code (ITU O.151). Each transmitter can start at any location on the stream and will last for a minimum of 1 channel to a maximum of 1 frame time (125 μ s). The BER receivers and transmitters are enabled by programming the RBEREN (bit 5) and TBEREN (bit 4) in the IMS register. In order to save power, the 16 transmitters and/or receivers can be disabled. (This is the default state.)

Multiple connection memory locations can be programmed for BER tests such that the BER patterns can be transmitted for multiple consecutive output channels. If consecutive input channels are not selected, the BER receiver will not compare the bit patterns correctly. The number of output channels which the BER pattern occupies has to be the same as the number of channels defined in the BER Length Register (BRLR) which defines how many BER channels are to be monitored by the BER receiver.

For each input stream, there is a set of registers for the BER test. The registers are as follows:

- BER Receiver Control Register (**BRCR**) ST[n]CBER (bit 1) is used to clear the Bit Receiver Error Register (BRER). ST[n]SBER (bit 0) is used to enable the per-stream BER receiver.
- BER Receiver Start Register (BRSR) ST[n]BRS7 0 (bit 7 0) defines the input channel from which the BER sequence will start to be compared.
- BER Receiver Length Register (BRLR) ST[n]BL8 0 (bit 8 0) define how many channels the sequence will last. Depending on the data rate being used, the BER test can last for a maximum of 32, 64,or 128 channels at the data rates of 2.048, 4.096,or 8.192.Mbps, respectively. The minimum length of the BER test is a single channel. The user must take care to program the correct channel length for the BER test so that the channel length does not exceed the total number of channels available in the stream.
- BER Receiver Error Register (BRER) This read-only register contains the number of counted errors. When
 the error count reaches 0xFFFF, the BER counter will stop updating so that it will not overflow. ST[n]CBER
 (bit 1) in the BER Receiver Control Register is used to reset the BRER register.

For normal BER operation, CMM (bit 0) must be 1 in the Connection Memory Low (CM_L) PCC1 - 0 (bits 2 - 1) in the Connection Memory Low must be programmed to "10" to enable the per-stream based BER transmitters. For each stream, the length (or total number of channels) of BER testing can be as long as one whole frame, but the channels MUST be consecutive. Upon completion of programming the connection memory, the corresponding BER receiver can be started by setting ST[n]SBER (bit 0) in the BRCR to high. There must be at least 2 frames (250 μ s) between completion of connection memory programming and starting the BER receiver before the BER receiver can correctly identify BER errors. A 16 bit BER counter is used to count the number of bit errors.



15.0 PCM A-law/μ-law Translation

The ZL50016 provides per-channel code translation to be used to adapt pulse code modulation (PCM) voice or data traffic between networks which use different encoding laws. Code translation is valid in both Connection Mode and Message Mode.

In order to use this feature the Connection Memory High (CM_H) entry for the output channel must be programmed. \overline{V}/D (bit 4) defines if the traffic in the channel is voice or data. Setting ICL1 - 0 (bits 3 - 2) programs the input coding law and OCL1 - 0 (bits 1- 0) programs the output coding law as shown in Table 9.

The different code options are:

Input Coding (ICL1- 0)	Output Coding (OCL1 - 0)	Voice Coding (V/D bit = 0)	Data Coding (V/D bit = 1)
00	00	ITU-T G.711 A-law	No code
01	01	ITU-T G.711 μ-law	Alternate Bit Inversion (ABI)
10	10	A-law without Alternate Bit Inversion (ABI)	Inverted Alternate Bit Inversion (ABI)
11	11	μ-law without Magnitude Inversion (MI)	All bits inverted

Table 9 - Input and Output Voice and Data Coding

For voice coding options, the ITU-T G.711 A-law and ITU-T G.711 μ -law are the standard rules for encoding. A-law without Alternate Bit Inversion (ABI) is an alternative code that does not invert the even bits (6, 4, 2, 0). μ -law without Magnitude Inversion (MI) is an alternative code that does not perform inversion of magnitude bits (6, 5, 4, 3, 2, 1, 0).

When transferring data code, the option "no code" does not invert the bits. The Alternate Bit Inversion (ABI) option inverts the even bits (6, 4, 2, 0) while the Inverted Alternate Bit Inversion (ABI) inverts the odd bits (7, 5, 3, 1). When the "All bits inverted" option is selected, all of the bits (7, 6, 5, 4, 3, 2, 1, 0) are inverted.

The input channel and output channel encoding law are configured independently. If the output channel coding is set to be different from the input channel, the ZL50016 performs translation between the two standards. If the input and output encoding laws are set to the same standard, no translation occurs. As the \overline{V}/D (bit 4) of the Connection Memory High (CM_H) must be set on a per-channel basis, it is not possible to translate between voice and data encoding laws.

16.0 Quadrant Frame Programming

By programming the Stream Input Quadrant Frame Registers (SIQFR0 - 15), users can divide one frame of input data into four quadrant frames and can force the LSB or MSB of every input channel in these quadrants to one or zero for robbed-bit signaling. The four quadrant frames are defined as follows:

Data Rate	Quadrant 0	Quadrant 1	Quadrant 2	Quadrant 3
2.048 Mbps	Channel 0 - 7	Channel 8 - 15	Channel 16 - 23	Channel 24 - 31
4.096 Mbps	Channel 0 - 15	Channel 16 - 31	Channel 32 - 47	Channel 48 - 63
8.192 Mbps	Channel 0 - 31	Channel 32 - 63	Channel 64 - 95	Channel 96 - 127
16.384 Mbps	Channel 0 - 63	Channel 64 - 127	Channel 128 - 191	Channel 192 - 255

Table 10 - Definition of the Four Quadrant Frames



When the quadrant frame control bits, STIN[n]Q3C2 - 0 (bit 11 - 9), STIN[n]Q2C2 - 0 (bit 8 - 6), STIN[n]Q1C2 - 0 (bit 5 - 3) or STIN[n]Q1C2 - 0 (bit 2 - 0), are set, the LSB or MSB of every input channel in the quadrant is forced to "1" or "0" as shown by the following table:

STIN[n]Q[y]C[2:0]	Action
0xx	Normal Operation
100	Replaces LSB of every channel in Quadrant y with '0'
101	Replaces LSB of every channel in Quadrant y with '1'
110	Replaces MSB of every channel in Quadrant y with '0'
111	Replaces MSB of every channel in Quadrant y with '1'
Note: y = 0, 1, 2, 3	

Table 11 - Quadrant Frame Bit Replacement

Note that Quadrant Frame Programming and BER reception cannot be used simultaneously on the same input stream.

17.0 JTAG Port

The JTAG test port is implemented to meet the mandatory requirements of the IEEE-1149.1 (JTAG) standard. The operation of the boundary-scan circuitry is controlled by an external Test Access Port (TAP) Controller.

17.1 Test Access Port (TAP)

The Test Access Port (TAP) accesses the ZL50016 test functions. It consists of three input pins and one output pin as follows:

- Test Clock Input (TCK) TCK provides the clock for the test logic. TCK does not interfere with any on-chip
 clock and thus remains independent in the functional mode. TCK permits shifting of test data into or out of
 the Boundary-Scan register cells concurrently with the operation of the device and without interfering with
 the on-chip logic.
- **Test Mode Selection Inputs (TMS)** The TAP Controller uses the logic signals received at the TMS input to control test operations. The TMS signals are sampled at the rising edge of the TCK pulse. This pin is internally pulled to high when it is not driven from an external source.
- **Test Data Input (TDi)** Serial input data applied to this port is fed either into the instruction register or into a test data register, depending on the sequence previously applied to the TMS input. The registers are described in a subsequent section. The received input data is sampled at the rising edge of the TCK pulse. This pin is internally pulled to high when it is not driven from an external source.
- Test Data Output (TDo) Depending on the sequence previously applied to the TMS input, the contents of either the instruction register or test data register are serially shifted out towards TDo. The data from TDo is clocked on the falling edge of the TCK pulses. When no data is shifted through the boundary scan cells, the TDo driver is set to a high impedance state.
- Test Reset (TRST) Resets the JTAG scan structure. This pin is internally pulled to high when it is not driven from an external source.



ZL50016 Data Sheet

17.2 Instruction Register

The ZL50016 uses the public instructions defined in the IEEE-1149.1 standard. The JTAG interface contains a four-bit instruction register. Instructions are serially loaded into the instruction register from the TDi when the TAP Controller is in its shifted-OR state. These instructions are subsequently decoded to achieve two basic functions: to select the test data register that may operate while the instruction is current and to define the serial test data register path that is used to shift data between TDi and TDo during data register scanning.

17.3 Test Data Registers

As specified in the IEEE-1149.1 standard, the ZL50016 JTAG interface contains three test data registers:

- The Boundary-Scan Register The Boundary-Scan register consists of a series of boundary-scan cells arranged to form a scan path around the boundary of the ZL50016 core logic.
- The Bypass Register The Bypass register is a single stage shift register that provides a one-bit path from TDi to TDo.
- The Device Identification Register The JTAG device ID for the ZL50016 is 0C36014B_H

Version	<31:28>	0000
Part Number	<27:12>	1100 0011 0110 0000
Manufacturer ID	<11:1>	0001 0100 101
LSB	<0>	1

17.4 BSDL

A Boundary Scan Description Language (BSDL) file is available from Microsemi Semiconductor to aid in the use of the IEEE-1149.1 test interface.



18.0 Register Address Mapping

Address A13 - A0	CPU Access	Register Name	Abbreviation	Reset By
0000 _H	R/W	Control Register	CR	Switch/Hardware
0001 _H	R/W	Internal Mode Selection Register	IMS	Switch/Hardware
0002 _H	R/W	Software Reset Register	SRR	Hardware Only
0003 _H	R/W	Output Clock and Frame Pulse Control Register	OCFCR	Hardware
0004 _H	R/W	Output Clock and Frame Pulse Selection Register	OCFSR	Hardware
0005 _H	R/W	FPo_OFF0 Register	FPOFF0	Hardware
0006 _H	R/W	FPo_OFF1 Register	FPOFF1	Hardware
0007 _H	R/W	FPo_OFF2 Register	FPOFF2	Hardware
0010 _H	R Only	Internal Flag Register	IFR	Switch/Hardware
0011 _H	R Only	BER Error Flag Register 0	BERFR0	Switch/Hardware
0013 _H	R Only	BER Receiver Lock Register 0	BERLR0	Switch/Hardware
0100 _H - 010F _H	R/W	Stream Input Control Registers 0 - 15	SICR0 - 15	Switch/Hardware
0120 _H - 012F _H	R/W	Stream Input Quadrant Frame Registers 0 - 15	SIQFR0 - 15	Switch/Hardware
0200 _H - 020F _H	R/W	Stream Output Control Registers 0 - 15	SOCR0 - 15	Switch/Hardware
0300 _H - 030F _H	R/W	BER Receiver Start Registers 0 - 15	BRSR0 - 15	Switch/Hardware
0320 _H - 032F _H	R/W	BER Receiver Length Registers 0 - 15	BRLR0 - 15	Switch/Hardware
0340 _H - 034F _H	R/W	BER Receiver Control Registers 0 - 15	BRCR0 - 15	Switch/Hardware
0360 _H - 036F _H	R Only	BER Receiver Error Registers 0 - 15	BRER0 - 15	Switch/Hardware

Table 12 - Address Map for Registers (A13 = 0)



19.0 Detailed Register Description

					Exte		ead/Wri eset Val)00 _H					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	OPM	0	FPIN POS	CKINP	FPINP	CKIN 1	CKIN 0	VAR EN	MBPE	OSB	MS1	MS0
Bit	N	ame						De	scripti	on					
15 - 12	Un	used	Reser	ved. I	n norma	al funct	ional m	ode, the	ese bits	MUS	r be se	et to zer	O.		
11	С	PM	This t	oit is u	ised to		device ating M	in Mast		e oper) Table	: 7, "Zl	_50016
10	Un	used	Reser	ved. l	n norma	al funct	ional m	ode, thi	s bits N	/JUST I	oe set	to zero.			
9	FPI	NPOS					, FPi str		frame Ì	bounda	ary (as	defined	-).
8	Cł	KINP	When	When this bit is high, FPi starts from frame boundary (as defined by GCI-Bus) Clock Input (CKi) Polarity When this bit is low, the CKi falling edge aligns with the frame boundary. When this bit is high, the CKi rising edge aligns with the frame boundary.											
7	FF	PINP	When	this bi	t is low,	the in	Polarity out fram ame pul	e pulse							at. When
6 - 5	CKI	N1 - 0	Input	Clock	(CKi) a	and Fr	ame Pu	lse (FP	i) Sele	ction					
					CK	IN1 - 0		FPi Act	ive Peri	od		CKi			
				_		00		6	1 ns		10	6.384 M	Hz		
						01		12	22 ns		8	3.192 MF	łz		
						10		24	4 ns		4	1.096 MF	łz		
						11				Reser	ved				
							DE_4M ² e the in				n "Pin	Descrip	tion" o	n pag	e 10,
4	VA	REN					Var ne varia he varia		y mod	e is dis	abled				
3	М	BPE				igh, the	Memory conne emory. \	ction mo	emory	block p	rograr	nming r			oled to mode is

Table 13 - Control Register (CR) Bits



					External	Read/Wr Reset Va)00 _H					
15	14	13	12	11	10 9	8	7	6	5	4	3	2	1	0
0	0	0	0	OPM	0 FPIN		FPINP	CKIN 1	CKIN 0	VAR EN	MBPE	OSB	MS1	MS0
Bit	Na	ame					De	escripti	on					
2	0	SB	This		es the STic					rial out	puts. Th	ne follo	owing t	table
		describes the HiZ control of the serial data outputs: RESET												
				0	Х	Х	Χ		HiZ			Drive	n High	
				1	1	Х	Х		HiZ			Drive	n High	
				1	0	0	Χ		HiZ			Drive	n High	
				1	0	1	0		HiZ				n High	
				1	0	1	1	(Cont	Active rolled b	y CM)	(C	Ac ontrolle	tive ed by C	CM)
				: Unused CR0 - 15 (output stro bit2 - 0).	eams are	tristate	d (STio	= HiZ,	STOF	· IZ = Dri	ven H	igh). F	Refer to
1 - 0	MS	31 - 0	Thes		ct Bits s are used by CPU:	to select	connec	ction me	emory	low, co	onnectic	n high	or da	ta mem-
				-	MS1 - 0			Memo	ry Sele	ction]	
					00		Connec	ction Me	mory Lo	ow Rea	d/Write		1	
					01		Connec	tion Me	mory Hi	gh Rea	nd/Write		1	
					10			Data N	1emory	Read				

Table 13 - Control Register (CR) Bits (continued)

Reserved

11



						Exte	rnal Read/ Reset			01 _H					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	STIO_ PD_EN	0	BDL	RBER EN	TBER EN	BPD 2	BPD 1	BPD 0	MBPS

	Т	ı			
Bit	Name			Description	
15 - 9	Unused	Reserved. In norma	al function	nal mode, these bits MUST be s	et to zero.
8	STIO_PD_ EN		the pull-	down resistors on all STio pads l-down resistors on all STio pad	
7	Unused	Reserved. In normal Used in this bi-direct		nal mode, these bits MUST be sode.	et to zero.
6	BDL	Bi-directional Conf	trol for S	treams 0-15	
			BDL	STio0 - 15 Operation	
			0	normal operation: STi0-15 are inputs STio0-15 are outputs	
			1	bi-directional operation: STi0-15 tied low internally STio0-15 are bi-directional	
5	RBEREN	When this bit is low	, all the B	PRBS Receiver Enable SER receivers are disabled. To e this bit MUST be high.	enable any BER receivers,
4	TBEREN	When this bit is		PRBS Transmitter Enable he BER transmitters are disable nsmitters, this bit MUST be high	•
3 - 1	BPD2 - 0	memory block progr ister is set to high a bits BPD2 - 0 are loa	the value amming and the Maded into	to be loaded into the connectifeature is activated. After the MIBPS bit in this register is set to bits 2 - 0 of the Connection Mem	BPE bit in the Control Reg- o high, the contents of the mory Low. Bits 15 - 3 of the

Table 14 - Internal Mode Selection Register (IMS) Bits



						Exte	ernal Read/ Reset			01 _H						
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
0	0	0	0	0	0	0	STIO_ PD_EN	0	BDL	RBER EN	TBER EN	BPD 2	BPD 1	BPD 0	MBPS	
Bit	N	lame							Descr	ription						
0	N	/IBPS	A M C	zero i IBPS a Ince th	to one and BF ne MB	transi PD2 - PE bi	ogramming ition of the object	nis bit s this reg Control	tarts the jister m Regist	ust be deter is s	defined et to h	in the	same e dev	write	operation	n. vo

Table 14 - Internal Mode Selection Register (IMS) Bits (continued)

ished, the MBPS bit returns to low, indicating the operation is completed. When MBPS

Whenever the microprocessor writes a one to the MBPS bit, the block programming function is started. As long as this bit is high, the user must maintain the same logical

is high, MBPS or MBPE can be set to low to abort the programming operation.

value to the other bits in this register to avoid any change in the device setting.

						I				dress: 0							
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
	0	0	0	0	0	0	0	0	0	0	0	0	0	0	SRST SW	0	
	1			T													
Bit	;	Nan	ne							Desc	criptio	n					
15 -	2	Unus	sed		erved ormal f	unctio	nal mo	ode, th	ese bi	ts MU\$	ST be	set to	zero.				
1		SRST	SW	s	witchir	ng bloc	ks are	witchi in so	ng blo tware	reset	e in no state.	rmal c Refer t	perati to Tabl	le 12,	hen this "Addres sters ar	s Map	for
0		Unus	sed		erved ormal f	unctio	nal mo	ode, th	ese bi	ts MU\$	ST be	set to	zero.				

Table 15 - Software Reset Register (SRR) Bits



ΕN

ZL50016 Data Sheet

						E	kternal Rea	ad/Write Adet Value:)3 _H					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	FPOF2 EN	FPOF1 EN	FPOF0 EN	0	0	CKO FPO3 EN	CKO FPO2 EN	CKO FPO1 EN	CKO FPO0 EN
Bit		Name	e						Descr	iption					
15 - 9	·														
8	F	POF2	EN					F	Po_OFF	2 Enab	le				

When this bit is high, output frame pulse FPo_OFF2 When this bit is low, output frame pulse FPo_OFF2. 7 FPOF1EN FPo_OFF1 Enable When this bit is high, output frame pulse FPo_OFF1 is enabled. When this bit is low, output frame pulse FPo OFF1 is in high impedance state. 6 FPOF0EN FPo OFF0 Enable When this bit is high, output frame pulse FPo OFF0 is enabled. When this bit is low, output frame pulse FPo OFF0 is in high impedance state. 5 Unused Reserved In normal functional mode, these bits **MUST** be set to zero. 4 Unused Reserved In normal functional mode, these bits **MUST** be set to zero. 3 CKOFPO3 CKo3 and FPo3 Enable When this bit is high, output clock CKo3 and output frame pulse FPo3 are enabled. ΕN When this bit is low, CKo3 and FPo3 are in high impedance state. 2 CKOFPO2 CKo2 and FPo2 Enable When this bit is high, output clock CKo2 and output frame pulse FPo2 are enabled. ΕN When this bit is low, CKo2 and FPo2 are in high impedance state. CKOFPO1 1 CKo1 and FPo1 Enable ΕN When this bit is high, output clock CKo1 and output frame pulse FPo1 are enabled. When this bit is low, CKo1 and FPo1 are in high impedance state. 0 CKOFPO0 CKo0 and FPo0 Enable

Table 16 - Output Clock and Frame Pulse Control Register (OCFCR) Bits

When this bit is high, output clock CKo0 and output frame pulse FPo0 are enabled.

When this bit is low, CKo0 and FPo0 are in high impedance state.



							l Read/W			4 _H					
						K	Reset Va								
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	FPO3 SEL1	CKO FPO3 SEL0	CKO3 P	FPO3 P	FPO3 POS	CKO2 P	FPO2 P	FPO2 POS	CKO1 P	FPO1 P	FPO1 POS	CKO0 P	FPO0 P	FPO0 POS
Bit		Name							Descri	ption					
15 - 14	4	Unused		eserve		onal mo	ode, the	ese bits	MUST	be set	to zero).			
13 - 12		CKOFPC SEL1 - (output ((CKo3)	Frequ	iency a	and O	utput F	rame	Pulse	(FPo3)	Pulse	Cycle
						CKOI SEL			FPo3		C	CKo3			
						0	0		244 ns	;	4.09	96 MHz			
						0			122 ns	;		92 MHz			
						1			61 ns 30 ns			84 MHz 68 MHz			
						•	•								
11		CKO3P	V	Output O Vhen thi Vhen thi	s bit is	low, the	e output	t clock (CKo3 fa						
10		FPO3P	V	Output F Vhen thi Vhen thi	s bit is	low, the	e outpu	t frame	pulse I	FPo3 h					
9	F	PO3PO	V	Output F Vhen thi Vhen thi	s bit is	low, FF	o3 stra	iddles f	rame b						
8		CKO2P	V	Output Co Vhen thi Vhen thi	s bit is	low, the	e output	t clock (CKo2 fa	-	-	-			•
7		FPO2P	V	Output F Vhen thi Vhen thi	s bit is	low, the	e outpu	t frame	pulse I	FPo2 h					
6	F	PO2PO	V	Output F Vhen thi Vhen thi	s bit is	low, FF	o2 stra	ıddles f	rame b						
5		CKO1P	V	Output Could the Market	s bit is	low, the	e output	clock (CKo1 fa						

Table 17 - Output Clock and Frame Pulse Selection Register (OCFSR) Bits

							Read/W			4 _H					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	CKO FPO3 SEL1	CKO FPO3 SEL0	3 P	FPO3 P	FPO3 POS	CKO2 P	FPO2 P	FPO2 POS	CKO1 P	FPO1 P	FPO1 POS	CKO0 P	FPO0 P	FPO0 POS
Bit		Name							Descri	ption					
4		FPO1P	١	Output F	s bit is	low, the	output	t frame	pulse F	Po1 h		-		•	

Bit	Name	Description
4	FPO1P	Output Frame Pulse (FPo1) Polarity Selection When this bit is low, the output frame pulse FPo1 has the negative frame pulse format. When this bit is high, the output frame pulse FPo1 has the positive frame pulse format.
3	FPO1POS	Output Frame Pulse (FPo1) Position When this bit is low, FPo1 straddles frame boundary (as defined by ST-BUS). When this bit is high, FPo1 starts from frame boundary (as defined by GCI-Bus).
2	CKO0P	Output Clock (CKo0) Polarity Selection When this bit is low, the output clock CKo0 falling edge aligns with the frame boundary. When this bit is high, the output clock CKo0 rising edge aligns with the frame boundary.
1	FPO0P	Output Frame Pulse (FPo0) Polarity Selection When this bit is low, the output frame pulse FPo0 has the negative frame pulse format. When this bit is high, the output frame pulse FPo0 has the positive frame pulse format.
0	FPO0POS	Output Frame Pulse (FPo0) Position When this bit is low, FPo0 straddles frame boundary (as defined by ST-BUS). When this bit is high, FPo0 starts from frame boundary (as defined by GCI-Bus).
i		

Note: In Divided Clock modes, CKo3 - 1 cannot exceed frequency of CKi.

Table 17 - Output Clock and Frame Pulse Selection Register (OCFSR) Bits (continued)



Reset Value: 0000 _H			
15 14 13 12 11 10 9 8 7 6 5 4	3 2	1	0
	F[n] FOF[n] F1 OFF0		FOF[n] C0

Bit	Name			Description	on		
15 - 10	Unused	Reserved.	In normal fu	inctional mode, these b	its MUST be set to	zero.	
9 - 2	FOF[n]OFF7 - 0	The binary		Offset se bits refers to the cha offset values depend or		-	me bound-
1 - 0	FOF[n]C1 - 0	FPo_OFF[n] Control b	oits			
		FOF[n]C 1-0	Data Rate (Mbps)	FPo_OFF[n] Pulse Cycle Width	FOF[n]OFF7 - 0 Permitted Channel Offset	Polarity Control	Position Control
		00	2.048	one 4.096 MHz clock	0 - 31	FPO0P	FPO0POS
		01	4.096	one 8.192 MHz clock	0 - 63	FPO1P	FPO1POS
		10	8.192	one 16.384 MHz clock	0 - 127	FPO2P	FPO2POS
		11	16.384	one 16.384 MHz clock	0 - 255	FPO2P	FPO2POS
Note: [n] d	enotes output offset	frame pulse fr	om 0 to 2.				

Table 18 - FPo_OFF[n] Register (FPo_OFF[n]) Bits



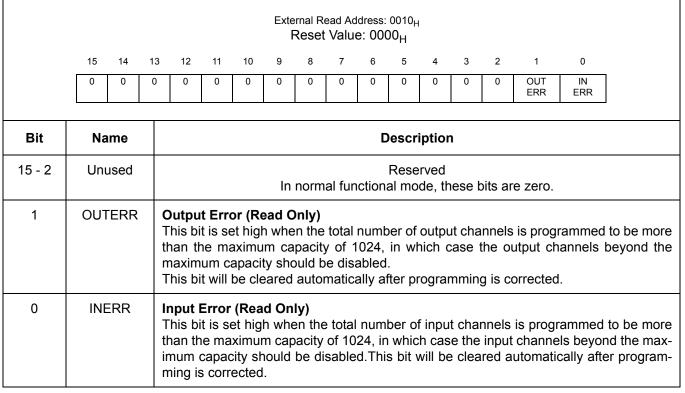


Table 19 - Internal Flag Register (IFR) Bits - Read Only

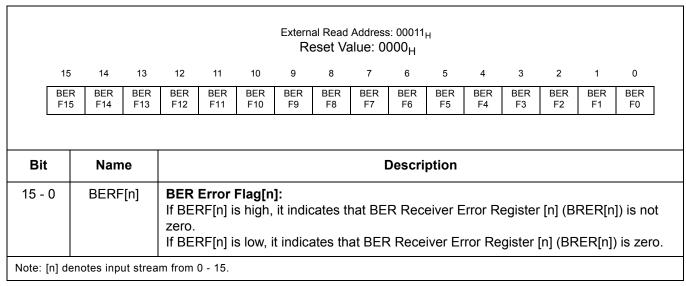


Table 20 - BER Error Flag Register 0 (BERFR0) Blts - Read Only



								al Read eset Va			Н					
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	BER L15	BER L14	BER L13	BER L12	BER L11	BER L10	BER L9	BER L8	BER L7	BER L6	BER L5	BER L4	BER L3	BER L2	BER L1	BER L0
		Nam	ıe						[Descri	ption					
Bit	•															

Table 21 - BER Receiver Lock Register 0 (BERLR0) Bits - Read Only



		External Read/\ Re	Vrite Address: 0 set Value: 0000				
15 14	13 12 11 10 9	9 8 7	6 5	4 3	2	1	0
0 0		STIN[n] STIN[n] BD2 BD1	STIN[n] STIN[n BD0 SMP1	STIN[n] STIN[n] SMP0 DR3	STIN[n] DR2	STIN[n] DR1	STIN[n] DR0
Bit	Name			Description			
15 - 9	Unused	In norm	nal functional mo	Reserved ode, these bits MU	JST be se	et to zero	
8 - 6	STIN[n]BD2 - 0	Input Stream[n] The binary value will be delayed re	of these bits ref	ers to the numbe te maximum value			
5 - 4	STIN[n]SMP1 - 0	Input Data Samp	oling Point Sele	ection Bits			
		STIN[n]SMP1-0		ampling Point 4.096 Mbps, 8.192 streams)	Mbps	(16.38	ng Point 4 Mbps ams)
		00		3/4 point		2/4	point
		01		1/4 point			
		10		2/4 point		4/4	point
		11		4/4 point			
3 - 0	STIN[n]DR3 - 0	Input Data Rate	Selection Bits:				
			STIN[n]DR3-0	Data Rat	е	7	
			0000	Stream Unu	ısed	1	
			0001	2.048 Mb	ps	1	
			0010	4.096 Mb	ps	1	
			0011	8.192 Mb	ps	1	
			0100	16.384 Mb	ps	1	
			0101 - 1111	Reserve	d		
Note: [n] deno	tes input stream from 0	- 15.					

Table 22 - Stream Input Control Register 0 - 15 (SICR0 - 15) Bits



					Externa	al Read/ Re		ddress: ue: 000		- 012F _H				
15 14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0 0	0	0	STIN[n] Q3C2	STIN[Q3C		STIN[n] Q2C2	STIN[n] Q2C1	STIN[n] Q2C0	STIN[n] Q1C2	STIN[n] Q1C1	STIN[n] Q1C0	STIN[n] Q0C2	STIN[n] Q0C1	STIN[n] Q0C0
Bit			Name		<u> </u>	1		1	Desci	ription		1		<u> </u>
15 - 12		L	Jnused			In norr	mal fund	ctional n		erved ese bits	MUST	be set	to zero.	
11 - 9	S	JNIT	[n]Q3C2	2 - 0	as Ch24		are use ch48 to	63, Ch9	ntrol STi 16 to 127	[n]'s quared 7 and Cl	adrant f h192 to	rame 3, 255 for	the 2.0	is defined 48 Mbps, ely.
						STIN[n 2-	-			Ope	ration			
					Ī	0x	Х			normal	operatio	n		
						10	0	LS	SB of eac	ch chann	el is rep	laced by	"0"	
						10	1	LS	SB of eac	ch chann	el is rep	laced by	"1"	
						11	0	M	SB of ea	ch chanr	nel is rep	laced by	′ "0"	
						11	1	M	SB of ea	ch chanr	nel is rep	laced by	′ "1"	
8 - 6	S	STIN	[n]Q2C2	2 - 0	as Ch16		Ch32 to	ed to cor 47, Ch	64 to 95	[n]'s qua	adrant f 1128 to	rame 2, 191 for	the 2.0	is defined 48 Mbps, ly.
						STII	N[n]Q2C 2-0			Ope	ration			
							0xx			normal	operatio	n		
							100	LS	SB of eac	ch chanr	nel is rep	laced by	"0"	
							101				•	laced by		
							110					laced by		
							111	M	SB of ea	ch chanr	nel is rep	laced by	/ " <mark>1"</mark>	

Table 23 - Stream Input Quadrant Frame Register 0 - 15 (SIQFR0 - 15) Bits

		External R	Read/Write Ad Reset Valu	ddress: 0120 _H - 012F _H ue: 0000 _H
15 14	13 12 11 10	9	8 7	6 5 4 3 2 1 0
0 0	0 0 STIN[n] STIN Q3C2 Q3C		TIN[n] STIN[n] Q2C2 Q2C1	STIN[n] STIN[n] STIN[n] STIN[n] STIN[n] STIN[n] STIN[n] STIN[n] Q000 <
Bit	Name			Description
5 - 3	STIN[n]Q1C2 - 0	as Ch8 to	bits are used 15, Ch16 to 3	Quadrant Frame 1 Control Bits d to control STi[n]'s quadrant frame 1, which is defined 31, Ch32 to 63 and Ch64 to 127 for the 2.048 Mbps, D2 Mbps, and 16.384 Mbps modes respectively.
			STIN[n]Q1C 2-0	Operation
			0xx	normal operation
			100	LSB of each channel is replaced by "0"
			101	LSB of each channel is replaced by "1"
			110	MSB of each channel is replaced by "0"
			111	MSB of each channel is replaced by "1"
2 - 0	STIN[n]Q0C2 - 0	as Ch0	e bits are used to 7, Ch0 to	Quadrant Frame 0 Control Bits d to control STi[n]'s quadrant frame 0, which is defined 15, Ch0 to 31 and Ch0 to 63 for the 2.048 Mbps, 22 Mbps, and 16.384 Mbps modes respectively.
			STIN[n]Q0C2	2-0 Operation
			0xx	normal operation
			100	LSB of each channel is replaced by "0"
			101	LSB of each channel is replaced by "1"
			110	MSB of each channel is replaced by "0"
			111	MSB of each channel is replaced by "1"
Note: [n] deno	tes input stream from 0	- 15.		

Table 23 - Stream Input Quadrant Frame Register 0 - 15 (SIQFR0 - 15) Bits (continued)



			⊏ X	uemai F		Vrite Ade set Valu			UZUFH				
15 14	13 12	11	10	9	8	7	6	5	4	3	2	1	0
0 0	0 0	STOHZ [n]A2	STOHZ [n]A1	STOHZ [n]A0	STO[n] FA1	STO[n] FA0	STO[n] AD2	STO[n] AD1	STO[n] AD0	STO[n] DR3	STO[n] DR2	STO[n] DR1	STO[n] DR0
Bit	Na	ame						Descri	iption				
15 - 12	Un	used		1		-1 £4:		Rese		MUOT		4	
44 0	0.7011	75 140	OT6			al functi			ese bits	MUSI	be set	to zero).
11 - 9	SIOHZ	Z[n]A2 - (Sic	JHZ Ad	aition	al Adva	nceme	nt Bits					
	(Valid only	y for STio0-7	·	STOHZ[n]A2-0		2.048 Mb	al Advan pps, 4.09 92 Mbps	6 Mbps				rancement streams)
				000				0 bit				0 bit	
				001				1/4 bit				2/4 b	
				010				2/4 bit				4/4 b	
				011 100				3/4 bit 4/4 bit				Reserv	ed .
				101-1	11			eserved	1				
				1011				COCIVCO					
8 - 7	STO[r	n]FA1 - 0	Out	put Str	eam[n] Fracti	onal A	dvance	ment l	3its)			
			S	STO[n]FA	1-0		.048 Mb	anceme ps, 4.09 lbps stre	6 Mbps	,		Advance 84 Mbps	ement s streams)
				00				0				0	
				01				1/4 bit				2/4	
				10				2/4 bit				Reser	ved
				11				3/4 bit					
6 - 4	STO[n]AD2 - 0	The is to	binary	value vance		bits ref	ers to th	ne num	ber of b			tput strea
3 - 0	STO[n]DR3 - 0	Out	put Dat	ta Rat	e Select	tion Bit	s					
					5	STIN[n]D	R3 - 0		Da	ata Rate	;		
						0000)			ed: STic Z driver			
						000	1		2.0	48 Mbp	s		
						0010)		4.0	96 Mbp	s		
						0011	ı		8.1	92 Mbp	S		
						0100)		16.	384 Mbp	os		

Table 24 - Stream Output Control Register 0 - 15 (SOCR0 - 15) Bits



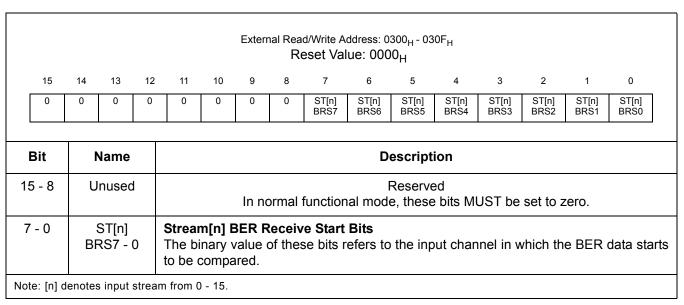


Table 25 - BER Receiver Start Register [n] (BRSR[n]) Bits

					Ex	ternal	Read/V Res		dress: (e: 0000 _l		03F _H				
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	ST[n] BL8	ST[n] BL7	ST[n] BL6	ST[n] BL5	ST[n] BL4	ST[n] BL3	ST[n] BL2	ST[n] BL1	ST[n] BL0
Bit		Name)						De	escripti	on				
15 - 9	ι	Jnuse	d			ln n	ormal fu	unction	-	Reserve , these	-	IST be	set to z	ero.	
8 - 0		ST[n] BL8 -		The b to rec 256 for respe	inary eive to or the ctively	value he BE data r y. The	R patterates of	e bits re rn. The 2.048 N m num	maximu /lbps, 4.	um num .096 Mb	ber of E ps, 8.1	BER cha 92 Mbp	annels is s and 1	s 32, 64 6.384 N	expected ,128 and //bps t to zero,
Note: [n] o	denote	es input	t strea	ım from	0 - 15.										

Table 26 - BER Receiver Length Register [n] (BRLR[n]) Bits



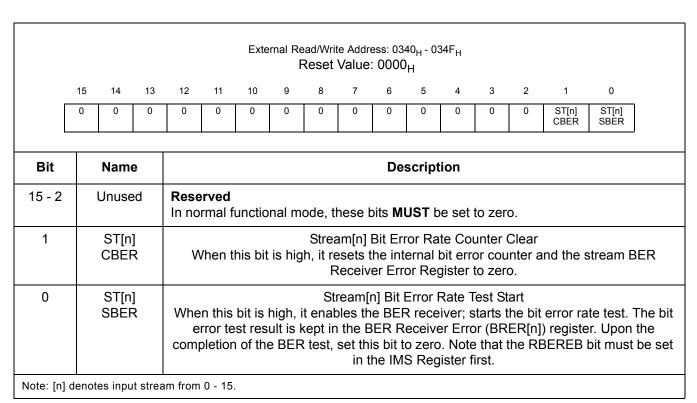


Table 27 - BER Receiver Control Register [n] (BRCR[n]) Bits

					E	External F	Read Add			6F _H					
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ST[n] BC15	ST[n] BC14	ST[n] BC13	ST[n] BC12	ST[n] BC11	ST[n] BC10	ST[n] BC9	ST[n] BC8	ST[n] BC7	ST[n] BC6	ST[n] BC5	ST[n] BC4	ST[n] BC3	ST[n] BC2	ST[n] BC1	ST[n] BC0
Bit	ı	Name						ı	Descrij	ption					
15 - 0		ST[n] C15 - 0	TI	tream[n ne binar um valu	y value	of the	se bits	refers	to the b					iches it	s maxi-
Note: [n]	denote	s input s	tream f	rom 0 - 1	5.										

Table 28 - BER Receiver Error Register [n] (BRER[n]) Bits - Read Only



Data Sheet



20.0 Memory

20.1 Memory Address Mappings

When A13 is high, the data or connection memory can be accessed by the microprocessor port. Bit 1 - 0 in the Control Register determine the access to the data or connection memory (CM_L or CM_H).

MSB (Note 1)				am Ado St0 - 1								nnel <i>F</i> Ch0 -	Addre: 255)	ss	
A13	A1 2	A1 1	A1 0	A9	A8	Stream [n]	A7	A6	A 5	A 4	А3	A2	A 1	Α0	Channel [n]
1 1 1 1 1 1 1 	0 0 0 0 0 0 0 0 0 	0 0 0 0 0 0 0 0 1	0 0 0 0 1 1 1 1 0	0 0 1 1 0 0 1 1 0	0 1 0 1 0 1 0 1 0	Stream 0 Stream 1 Stream 2 Stream 3 Stream 4 Stream 5 Stream 6 Stream 7 Stream 8	0 0 0 0 0 0	0 0 0 0 0 0 0 0 0 0 0	0 0 0 0 1 1	0 0 1 1 0 0	0 0 1 1 0 0	0 0 1 1 0 0	0 0 1 1 0 0	0 1 0 1 0 1	Ch 0 Ch 1 Ch 30 Ch 31 (Note 2) Ch 32 Ch 33 Ch 62 Ch 63 (Note 3) Ch 62 Ch 63 (Note 4) Ch 127 (Note 4) Ch 254
							1 1	1 1	1 1	1 1	1 1	1 1	1 1	0 1	Ch 255 (Note 5)

Note 1: Notes:A13 must be high for access to data and connection memory positions. A13 must be low to access internal registers.

Table 29 - Address Map for Memory Locations (A13 = 1)

Note 2: Channels 0 to 31 are used when serial stream is at 2.048 Mbps.

Note 3: Channels 0 to 63 are used when serial stream is at 4.096 Mbps.

Note 4: Channels 0 to 127 are used when serial stream is at 8.192 Mbps.

Note 5: Channels 0 to 255 are used when serial stream is at 16.384 Mbps.



20.2 Connection Memory Low (CM_L) Bit Assignment

When the CMM bit (bit 0) in the connection memory low is zero, the per-channel transmission is set to the normal channel-switching. The connection memory low bit assignment for the channel transmission mode is shown in Table 30 on page 55.

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	UA EN	V/C	0	SSA 3	SSA 2	SSA 1	SSA 0	SCA 7	SCA 6	SCA 5	SCA 4	SCA 3	SCA 2	SCA 1	SCA 0	CMM =0
Bit		Name								Desc	riptio	n				
15		UAEN		high w	this bit ill be i this bi	t is low gnored t is hig	, norm d. jh, swi	nal swi tch wit	tch wit h μ-la	thout µ	ı-law/ <i>F</i>					ection men
14		V/C		memor	this bi 'y. this bi	t is lov t is se	v, the o	output gh, the	data f	ıt data	for thi	is chai	nnel w	ill be t	aken 1	nstant del from varia
13	ı	Unused	d	Reserv	/ed. Ir	norm	nal fun	ctiona	mode	e, thes	e bits	MUST	Γbe se	et to z	ero.	
12 - 9	5	SSA3 -	0	Source The bir		-		_	repre	esents	the in	put str	ream r	numbe	er.	
8 - 1	S	SCA7 -	0	Source The bir					repre	esents	the in	put ch	annel	numb	er.	
0	C	CMM =	-	Conne						:a :a 41	ne nor		ما مامان		l- D''	

Table 30 - Connection Memory Low (CM_L) Bit Assignment when CMM = 0



When CMM is one, the device is programmed to perform one of the special per-channel transmission modes. Bits PCC0 and PCC1 from connection memory are used to select the per-channel tristate, message or BER test mode as shown in Table 31 on page 56.

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	UA EN	0	0	0	0	MSG 7	MSG 6	MSG 5	MSG 4	MSG 3	MSG 2	MSG 1	MSG 0	PCC 1	PCC 0	CMM =1
Bit		Nar	ne							D	escrip	tion				
15		UA	ΞN	V 0 V	Vhen ry hiç Vhen	this bigh will this bight	t is low be igno t is hig	, mess ored. h, mes	age m sage r	ode ha node h	ıs no μ	-law/A- aw/A-la	law co	nversi		nnection
14 - 11		Unu	sed				In nor	mal fu	nction		Reserve, thes		MUST	be set	to zero).
10 - 3	ı	MSG	7 - 0	8		lata for	ta Bits the m		e mode	e. Not ı	used in	the pe	er-char	nnel tris	state a	nd BER t
2 - 1		PCC ⁻	1 - 0				I Cont its conf			spondi	ng entr	y's val	ue on	the ST	io strea	am.
2 - 1		PCC ⁻	1 - 0					trol the	corre		ng entr			the ST	io strea	am.
2 - 1		PCC ⁻	1 - 0				its cont	trol the	corres	Char		tput Mc	ode	the STi	io strea	am.
2 - 1		PCC ²	1 - 0				PC C1	trol the	corres	Char Per	nnel Ou	tput Mo	ode	the ST	io strea	am.
2 - 1		PCC [,]	1 - 0				PC C1	trol the	corres	Char Per	nnel Ou Channe	tput Mo	ode	the ST	io strea	am.
2 - 1		PCC ²	1 - 0				PC C1 0	trol the	C 0	Char Per	nnel Ou Channe lessage	tput Mo el Trista e Mode t Mode	ode	the ST	io strea	am.
2 - 1		PCC ²		C	onne this	etwo b	PC	P P C C C C C C C C C C C C C C C C C C	corres	Char Per M B	Channel Ou Channel lessage ER Tes Reser	tput Moel Tristae Mode t Mode ved	nde ite	I control		e which i

Table 31 - Connection Memory Low (CM_L) Bit Assignment when CMM = 1

20.3 Connection Memory High (CM_H) Bit Assignment

Connection memory high provides the detailed information required for μ -law and A-law conversion. ICL and OCL bits describe the Input Coding Law and the Output Coding Law, respectively. They are used to select the expected PCM coding laws for the connection, on the TDM inputs, and on the TDM outputs. The \overline{V}/D bit is used to select the class of coding law. If the \overline{V}/D bit is cleared (to select a voice connection), the ICL and OCL bits select between A-law and μ -law specifications related to G.711 voice coding. If the \overline{V}/D bit is set (to select a data connection), the ICL and OCL bits select between various bit inverting protocols. These coding laws are illustrated in the following table. If the ICL is different than the OCL, all data bytes passing through the switch on that particular connection are translated between the indicated laws. If the ICL and the OCL are the same, no coding law translation is performed.



The ICL, the OCL bits and \overline{V}/D bit only have an effect on PCM code translations for constant delay connections, variable delay connections and per-channel message mode.

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	0	0	0	0	0	0	0	0	0	0	V/D	ICL 1	ICL 0	OCL 1	OCL 0
Bit		Name								Desc	riptio	n				
15 - 5		Unuse	d			ln n	ormal	functio	nal m		erved nese b		JST be	e set to	o zero.	
4		V/D		When	/Data (this bi this bi	t is lo	w, the									
3 - 2		ICL1 -	0	Input	Codin	g Lav	V.									
					ICL1	-0					ding La					
								oice (V		,	For	Data (= 1)		
					00			JTI.TTI					code			
					01			ITT.ITU	-	/			BI			
					10			-law w/					ed ABI			
					11		μ-lav	v w/o M Invers		de	,	All Bits	Inverte	ed		
1 - 0	(DCL1 -	0	Outp	ut Cod	ing L	aw									
									Ou	tput Co	oding L	aw				
					OCI	_1-0	For '	Voice (//D bit	= 0)	For	Data (//D bit	= 1)		
					0	0	С	CITT.IT	U A-la	W		No	code			
					0	1	С	CITT.IT	U μ-la	w		Α	BI			
					1	0	,	A-law w	/o ABI			Inverte	ed ABI			
					1	1	μ-la	w w/o I		ude	A	All Bits	Inverte	d		

Note 1: For proper μ -law/A-law conversion, the CM_H bits should be set before Bit 15 of CM_L is set to high. Note 2: Refer to G.711 standard for detail information of different laws.

Table 32 - Connection Memory High (CM_H) Bit Assignment



21.0 DC Parameters

Absolute Maximum Ratings*

	Parameter	Symbol	Min.	Max.	Units
1	I/O Supply Voltage	V _{DD_IO}	-0.5	5.0	V
2	Core Supply Voltage	V _{DD_CORE}	-0.5	2.5	V
3	Input Voltage	V _{I_3V}	-0.5	V _{DD} + 0.5	V
4	Input Voltage (5 V-tolerant inputs)	V _{I_5V}	-0.5	7.0	V
5	Continuous Current at Digital Outputs	Io		15	mA
6	Package Power Dissipation	P _D		1.5	W
7	Storage Temperature	T _S	- 55	+125	°C

^{*} Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

$\textbf{Recommended Operating Conditions -} \ \textit{Voltages are with respect to ground (V_{SS}) unless otherwise stated.}$

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units
1	Operating Temperature	T _{OP}	-40	25	+85	°C
2	Positive Supply	V_{DD_IO}	3.0	3.3	3.6	V
3	Positive Supply	V _{DD_CORE}	1.71	1.8	1.89	V
4	Input Voltage	V _I	0	3.3	V_{DD_IO}	V
5	Input Voltage on 5 V-Tolerant Inputs	V _{I_5V}	0	5.0	5.5	V

[‡] Typical figures are at 25°C and are for design aid only: not guaranteed and not subject to production testing.

DC Electrical Characteristics[†] - Voltages are with respect to ground (V_{ss}) unless otherwise stated.

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	Supply Current - V _{DD_CORE}	I _{DD_CORE}			115	mA	
2	Supply Current - V _{DD_IO}	I _{DD_IO}			40	mA	C _L =30pF
3	Input High Voltage	V_{IH}	2.0			V	
4	Input Low Voltage	V _{IL}			0.8	V	
5	Input Leakage (input pins) Input Leakage (bi-directional pins)	I _{IL} I _{BL}			5 5	μ Α μ Α	0≤ <v<sub>IN≤V_{DD_IO} See Note 1</v<sub>
6	Weak Pullup Current	I _{PU}		-33		μΑ	Input at 0 V
7	Weak Pulldown Current	I _{PD}		33		μΑ	Input at V _{DD_IO}
8	Input Pin Capacitance	C _I		3		pF	
9	Output High Voltage	V _{OH}	2.4			V	I _{OH} = 8 mA
10	Output Low Voltage	V _{OL}			0.4	V	I _{OL} = 8 mA
11	Output High Impedance Leakage	I _{OZ}			5	μΑ	0 < V < V _{DD}
12	Output Pin Capacitance	C _O		5	10	pF	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

^{*} Note 1: Maximum leakage on pins (output or I/O pins in high impedance state) is over an applied voltage (V_{IN}) .



22.0 AC Parameters

AC Electrical Characteristics[†] - Timing Parameter Measurement Voltage Levels

	Characteristics	Sym.	Level	Units	Conditions
1	CMOS Threshold	V _{CT}	0.5 V _{DD_IO}	٧	
2	Rise/Fall Threshold Voltage High	V_{HM}	0.7 V _{DD_IO}	V	
3	Rise/Fall Threshold Voltage Low	V_{LM}	0.3 V _{DD_IO}	V	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

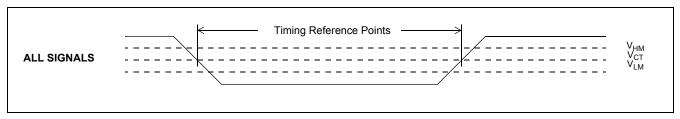


Figure 19 - Timing Parameter Measurement Voltage Levels



AC Electrical Characteristics[†] - Motorola Non-Multiplexed Bus Mode - Read Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	DS de-asserted time	t _{DSD}	15			ns	
3	CS setup to DS falling	t _{CSS}	0			ns	
4	R/W setup to DS falling	t _{RWS}	10			ns	
5	Address setup to DS falling	t _{AS}	5			ns	
6	CS hold after DS rising	t _{CSH}	0			ns	
7	R/W hold after DS rising	t _{RWH}	0			ns	
8	Address hold after DS rising	t _{AH}	0			ns	
9	Data setup to DTA Low	t _{DS}	8			ns	C _L = 50 pF
10	Data Active to High Impedance	t _{DHZ}			8	ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
11	Acknowledgement delay time. From DS low to DTA low: Registers Memory	t _{AKD}			75 185	ns ns	C _L = 50 pF C _L = 50 pF
12	Acknowledgement hold time. From DS high to DTA high	t _{AKH}	4		12	ns	C _L = 50 pF, R _L = 1 K (Note 1)
13	DTA drive high to HiZ	t _{AKZ}			8	ns	

Note 1: High impedance is measured by pulling to the appropriate rail with R_L , with timing corrected to cancel time taken to discharge C_L .

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

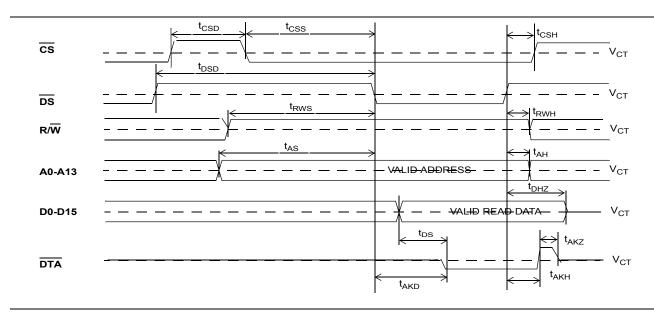


Figure 20 - Motorola Non-Multiplexed Bus Timing - Read Access

Note 2: A delay of $500 \mu s$ to 2 ms (see Section 13.2 on page 32) must be applied before the first microprocessor access is performed after the RESET pin is set high.

[†] Characteristics are over recommended operating conditions unless otherwise stated.



AC Electrical Characteristics[†] - Motorola Non-Multiplexed Bus Mode - Write Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	DS de-asserted time	t _{DSD}	15			ns	
3	CS setup to DS falling	t _{CSS}	0			ns	
4	R/W setup to DS falling	t _{RWS}	10			ns	
5	Address setup to DS falling	t _{AS}	5			ns	
6	Data setup to DS falling	t _{DS}	0			ns	C _L = 50 pF
7	CS hold after DS rising	t _{CSH}	0			ns	
8	R/W hold after DS rising	t _{RWH}	0			ns	
9	Address hold after DS rising	t _{AH}	0			ns	
10	Data hold from DS rising	t _{DH}	5			ns	C _L = 50 pF, R _L = 1 K (Note 1)
11	Acknowledgement delay time. From DS low to DTA low: Registers Memory	t _{AKD}			55 150	ns ns	C _L = 50 pF C _L = 50 pF
12	Acknowledgement hold time. From DS high to DTA high	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF, } R_L = 1 \text{ K}$ (Note 1)
13	DTA drive high to HiZ	t _{AKZ}			8	ns	

High impedance is measured by pulling to the appropriate rail with R_I, with timing corrected to cancel time taken to discharge C_L.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

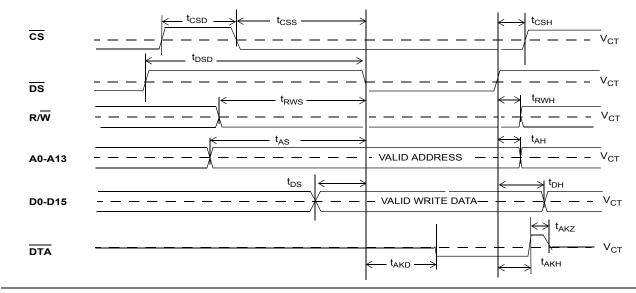


Figure 21 - Motorola Non-Multiplexed Bus Timing - Write Access

A delay of $500 \mu s$ to 2 ms (see Section 13.2 on page 32) must be applied before the first microprocessor access is Note 2: performed after the RESET pin is set high.

[†] Characteristics are over recommended operating conditions unless otherwise stated.



AC Electrical Characteristics[†] - Intel Non-Multiplexed Bus Mode - Read Access

	Characteristics	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	RD setup to CS falling	t _{RS}	10			ns	
3	WR setup to CS falling	t _{WS}	10			ns	
4	Address setup to CS falling	t _{AS}	5			ns	
5	RD hold after CS rising	t _{RH}	0			ns	
6	WR hold after CS rising	t _{WH}	0			ns	
7	Address hold after CS rising	t _{AH}	0			ns	
8	Data setup to RDY high	t _{DS}	8			ns	C _L = 50 pF
9	Data Active to High Impedance	t _{CSZ}	7			ns	C _L = 50 pF, R _L = 1 K (Note 1)
10	Acknowledgement delay time. From CS low to RDY high: Registers Memory	t _{AKD}			175 185	ns ns	C _L = 50 pF
							C _L = 50 pF
11	Acknowledgement hold time. From CS high to RDY low	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
12	RDY drive low to HiZ	t _{AKZ}			8	ns	

High impedance is measured by pulling to the appropriate rail with R_{L} , with timing corrected to cancel time taken to Note 1: discharge C_L

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

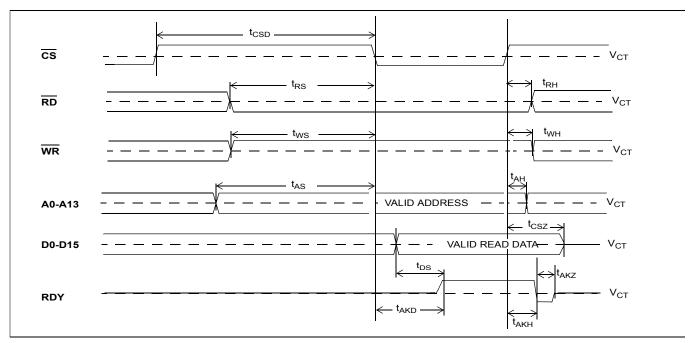


Figure 22 - Intel Non-Multiplexed Bus Timing - Read Access

A delay of $500~\mu s$ to 2 ms (see Section 13.2 on page 32) must be applied before the first microprocessor access is Note 2: performed after the RESET pin is set high.

[†] Characteristics are over recommended operating conditions unless otherwise stated.



AC Electrical Characteristics[†] - Intel Non-Multiplexed Bus Mode - Write Access

	Characteristics	Sym.	Min.	Typ. [‡]	Max.	Units	Test Conditions ²
1	CS de-asserted time	t _{CSD}	15			ns	
2	WR setup to CS falling	t _{WS}	10			ns	
3	RD setup to CS falling	t _{RS}	10			ns	
4	Address setup to CS falling	t _{AS}	5			ns	
5	Data setup to CS falling	t _{DS}	0			ns	C _L = 50 pF
6	WR hold after CS rising	t _{WH}	0			ns	
7	RD hold after CS rising	t _{RH}	0			ns	
8	Address hold after CS rising	t _{AH}	10			ns	
9	Data hold after CS rising	t _{DH}	5			ns	$C_L = 50 \text{ pF}, R_L = 1 \text{ K}$ (Note 1)
10	Acknowledgement delay time. From CS low to RDY high: Registers Memory	t _{AKD}			55 150	ns ns	C _L = 50 pF C _L = 50 pF
11	Acknowledgement hold time. From CS high to RDY low	t _{AKH}	4		12	ns	$C_L = 50 \text{ pF, } R_L = 1 \text{ K}$ (Note 1)
12	RDY drive low to HiZ	t _{AKZ}			8	ns	

High impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to Note 1: discharge C_L.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

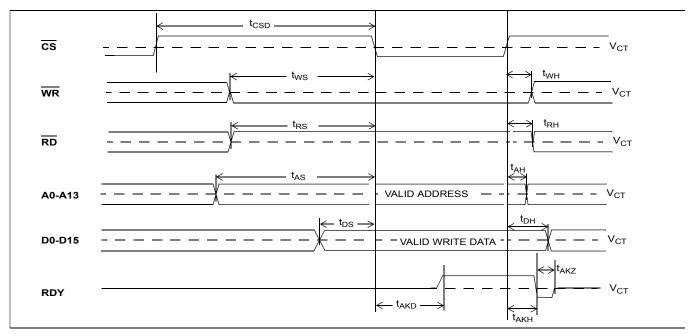


Figure 23 - Intel Non-Multiplexed Bus Timing - Write Access

A delay of $500 \mu s$ to 2 ms (Section 13.2 on page 32) must be applied before the first microprocessor access is performed Note 2: after the RESET pin is set high.

[†] Characteristics are over recommended operating conditions unless otherwise stated.



AC Electrical Characteristics[†] - JTAG Test Port Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	TCK Clock Period	t _{TCKP}	100			ns	
2	TCK Clock Pulse Width High	t _{TCKH}	20			ns	
3	TCK Clock Pulse Width Low	t _{TCKL}	20			ns	
4	TMS Set-up Time	t _{TMSS}	10			ns	
5	TMS Hold Time	t _{TMSH}	10			ns	
6	TDi Input Set-up Time	t _{TDIS}	20			ns	
7	TDi Input Hold Time	t _{TDIH}	60			ns	
8	TDo Output Delay	t _{TDOD}			30	ns	C _L = 30 pF
9	TRST pulse width	t _{TRSTW}	200			ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

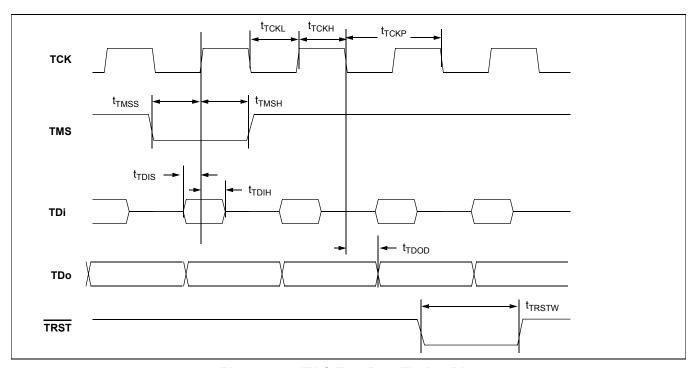


Figure 24 - JTAG Test Port Timing Diagram



AC Electrical Characteristics[†] - FPi and CKi Timing when CKIN1-0 bits = 00 (16.384 MHz)

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	40	61	115	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	20			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	20			ns	
4	CKi Input Clock Period	t _{CKIP}	55	61	67	ns	
5	CKi Input Clock High Time	t _{CKIH}	27		34	ns	
6	CKi Input Clock Low Time	t _{CKIL}	27		34	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPi and CKi Timing when CKIN1-0 bits = 01 (8.192 MHz)

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	90	122	220	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	45			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	45			ns	
4	CKi Input Clock Period	t _{CKIP}	110	122	135	ns	
5	CKi Input Clock High Time	t _{CKIH}	55		69	ns	
6	CKi Input Clock Low Time	t _{CKIL}	55		69	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.



AC Electrical Characteristics[†] - FPi and CKi Timing when CKIN1-0 bits = 10 (4.096 MHz)

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPi Input Frame Pulse Width	t _{FPIW}	90	244	420	ns	
2	FPi Input Frame Pulse Setup Time	t _{FPIS}	110			ns	
3	FPi Input Frame Pulse Hold Time	t _{FPIH}	110			ns	
4	CKi Input Clock Period	t _{CKIP}	220	244	270	ns	
5	CKi Input Clock High Time	t _{CKIH}	110		135	ns	
6	CKi Input Clock Low Time	t _{CKIL}	110		135	ns	
7	CKi Input Clock Rise/Fall Time	t _r CKi, t _f CKi			3	ns	
8	CKi Input Clock Cycle to Cycle Variation	t _{CVC}	0		20	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

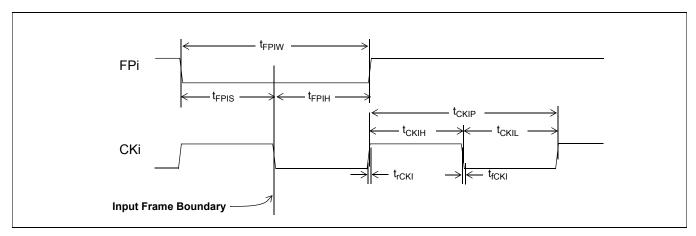


Figure 25 - Frame Pulse Input and Clock Input Timing Diagram (ST-BUS)

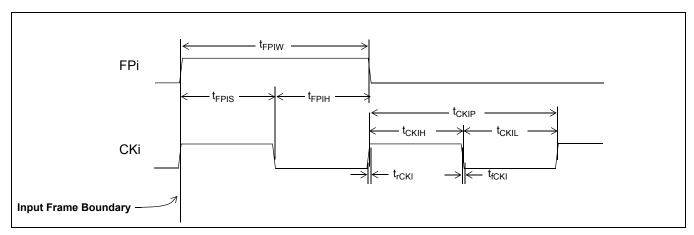


Figure 26 - Frame Pulse Input and Clock Input Timing Diagram (GCI-Bus)



AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Input Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	STi Setup Time						
	2.048 Mbps 4.096 Mbps 8.192 Mbps 16.384 Mbps	t _{SIS2} t _{SIS4} t _{SIS8} t _{SIS16}	5 5 5 5			ns ns ns ns	
2	STi Hold Time 2.048 Mbps 4.096 Mbps 8.192 Mbps 16.384 Mbps	t _{SIH2} t _{SIH4} t _{SIH8} t _{SIH16}	8 8 8			ns ns ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

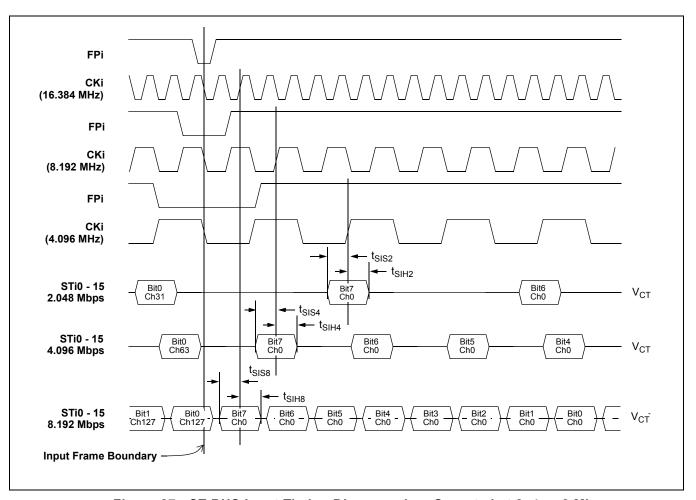
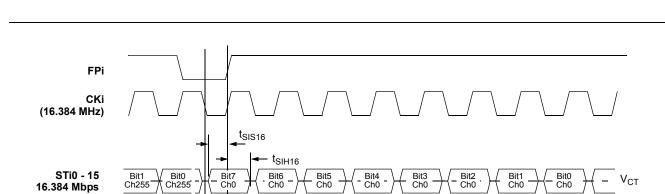


Figure 27 - ST-BUS Input Timing Diagram when Operated at 2, 4 or 8 Mbps



Microsemi

Input Frame Boundary

Figure 28 - ST-BUS Input Timing Diagram when Operated at 16 Mbps

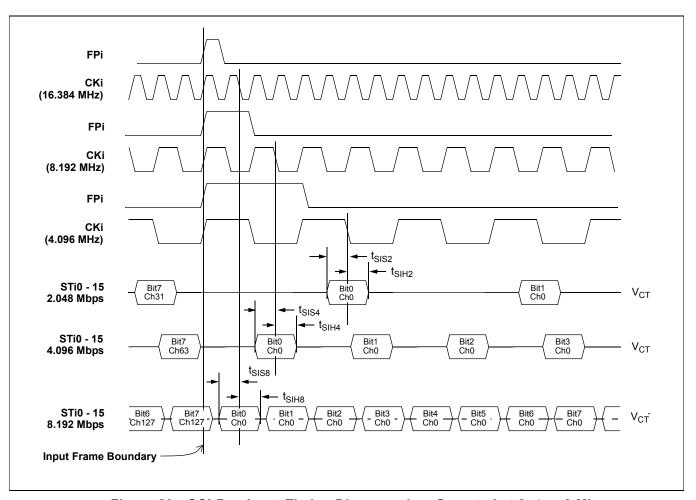


Figure 29 - GCI-Bus Input Timing Diagram when Operated at 2, 4 or 8 Mbps

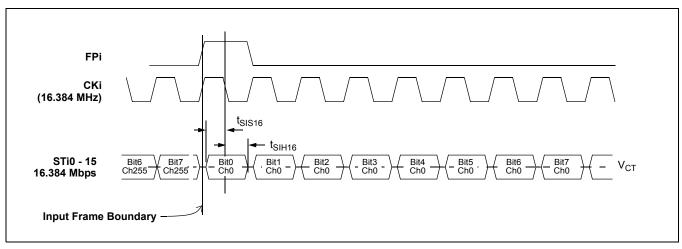


Figure 30 - GCI-Bus Input Timing Diagram when Operated at 16 Mbps



Data Sheet

AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Output Timing

Microsemi.

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions
1	STio Delay - Active to Active						C _L = 30 pF
	@2.048 Mbps @4.096 Mbps @8.192 Mbps @16.384 Mbps	t _{SOD2} t _{SOD4} t _{SOD8} t _{SOD16}	0 0 0 0		6 6 6	ns ns ns ns	Multiplied Clock Mode
	@2.048 Mbps @4.096 Mbps @8.192 Mbps @16.384 Mbps	t _{SOD2} t _{SOD4} t _{SOD8} t _{SOD16}	-6 -6 -6		0 0 0	ns ns ns ns	Divided Clock Mode

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

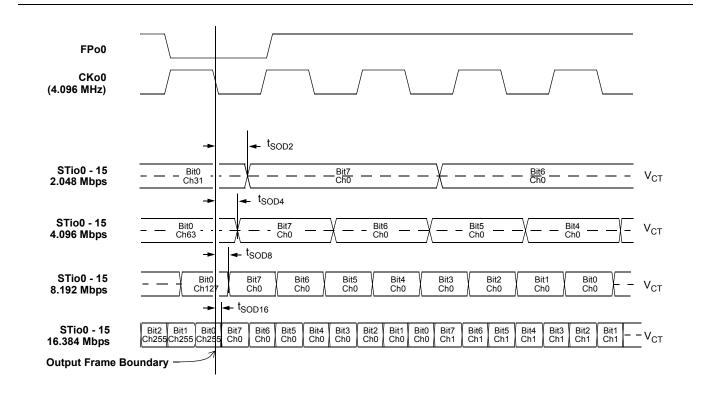


Figure 31 - ST-BUS Output Timing Diagram when Operated at 2, 4, 8 or 16 Mbps



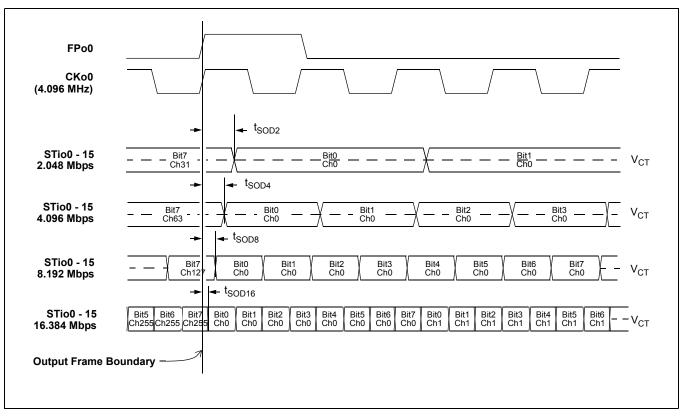


Figure 32 - GCI-Bus Output Timing Diagram when Operated at 2, 4, 8 or 16 Mbps



AC Electrical Characteristics[†] - ST-BUS/GCI-Bus Output Tristate Timing

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Test Conditions*
1	STio Delay - Active to High-Z	t _{DZ}	-3 -8		7 0	ns ns	Multiplied Clock Mode Divided Clock Mode
2	STio Delay - High-Z to Active	t _{ZD}	-3 -8		7 0	ns ns	Multiplied Clock Mode Divided Clock Mode
3	Output Drive Enable (ODE) Delay - High-Z to Active	t _{ZD_ODE}			77	ns	Multiplied Clock Mode
	CKi @ 4.096 MHz CKi @ 8.192 MHz CKi @ 16.384 MHz				260 138 77	ns ns ns	Divided Clock Mode

[†] Characteristics are over recommended operating conditions unless otherwise stated.

Note 1: High impedance is measured by pulling to the appropriate rail with R_L , with timing corrected to cancel the time taken to discharge C_L .

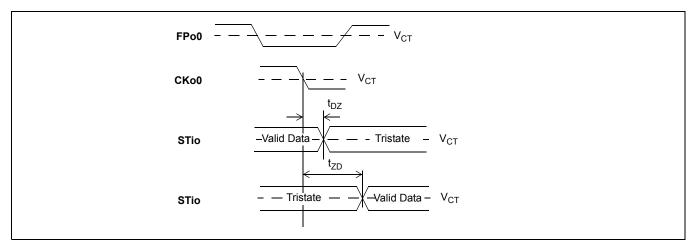


Figure 33 - Serial Output and External Control

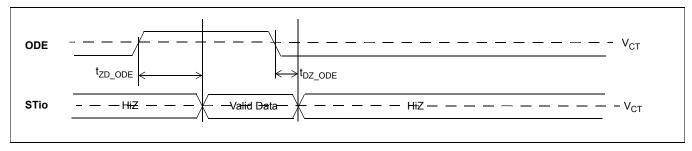


Figure 34 - Output Drive Enable (ODE)

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.



AC Electrical Characteristics[†] - Clock Mode Input/Output Frame Boundary Alignment

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	Input and Output Frame Offset in Divided Clock Mode	t _{FBOS}	5		13	ns	
2	Input and Output Frame Offset in Multiplied Clock Mode	t _{FBOS}	2		10	ns	Input reference jitter is equal to zero.

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

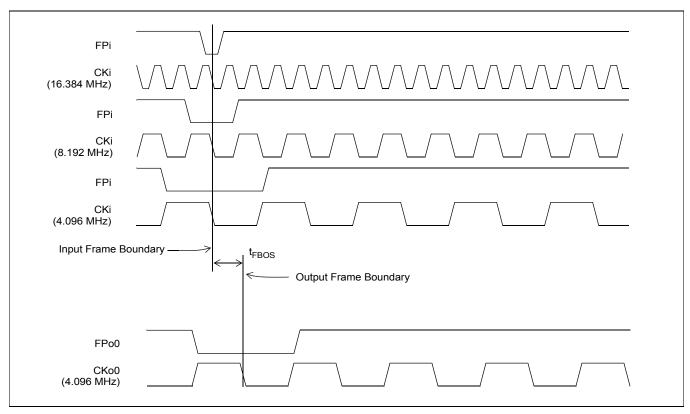


Figure 35 - Input and Output Frame Boundary Offset



Data Sheet

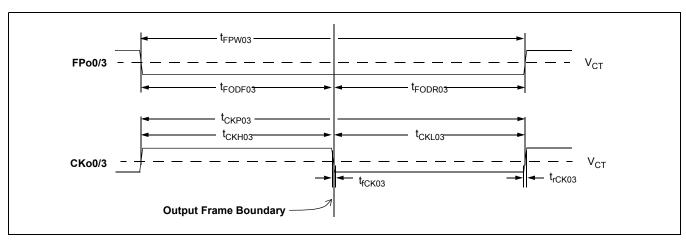


Figure 36 - FPo0 and CKo0 Timing Diagram

AC Electrical Characteristics[†] - FPo0/CKo0 and FPo3/CKo3 (4.096 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo0 Output Pulse Width	t _{FPW03}	239	244	249	ns	
2	FPo0 Output Delay from the FPo0 falling edge to the output frame boundary	t _{FODF03}	117		127	ns	$C_L = 30 pF$
3	FPo0 Output Delay from the output frame boundary to the FPo0 rising edge	t _{FODR03}	117		127	ns	
4	CKo0 Output Clock Period	t _{CKP03}	239	244	249	ns	
5	CKo0 Output High Time	t _{CKH03}	117		127	ns	$C_L = 30 pF$
6	CKo0 Output Low Time	t _{CKL03}	117		127	ns	
7	CKo0 Output Rise/Fall Time	t _{rCK03} , t _{fCK03}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

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AC Electrical Characteristics[†] - FPo0/CKo0 and FPo3/CKo3 (4.096 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
	3110101010	- - - - - - - - - -		. 7 (-)	11161711	01110	
1	FPo0 Output Pulse Width	t _{FPW03}	218	244	270	ns	
2	FPo0 Output Delay from the FPo0 falling edge to the output frame boundary	t _{FODF03}	117		127	ns	C _L = 30 pF
3	FPo0 Output Delay from the output frame boundary to the FPo0 rising edge	t _{FODR03}	97		146	ns	
4	CKo0 Output Clock Period	t _{CKP03}	218	244	270	ns	
5	CKo0 Output High Time	t _{CKH03}	117		127	ns	$C_L = 30 pF$
6	CKo0 Output Low Time	t _{CKL03}	97		146	ns	
7	CKo0 Output Rise/Fall Time	t _{rCK03} , t _{fCK03}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.



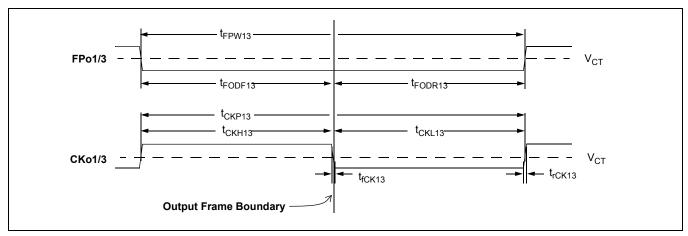


Figure 37 - FPo1/3 and CKo1/3 Timing Diagram

AC Electrical Characteristics[†] - FPo1/CKo1 and FPo3/CKo3 (8.192 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo1 Output Pulse Width	t _{FPW13}	117	122	127	ns	
2	FPo1 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF13}	56		66	ns	C _L = 30 pF
3	FPo1 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR13}	56		66	ns	
4	CKo1 Output Clock Period	t _{CKP13}	117	122	127	ns	
5	CKo1 Output High Time	t _{CKH13}	56		66	ns	$C_L = 30 pF$
6	CKo1 Output Low Time	t _{CKL13}	56		66	ns	
7	CKo1 Output Rise/Fall Time	t _{rCK13} , t _{fCK13}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo1/CKo1 and FPo3/CKo3 (8.192 MHz) Timing for Multiplied Clock Mode with More than 10ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ. [‡]	Max.	Units	Notes
1	FPo1 Output Pulse Width	t _{FPW13}	106	122	127	ns	
2	FPo1 Output Delay from the FPo1 falling edge to the output frame boundary	t _{FODF13}	56		66	ns	C _L = 30 pF
3	FPo1 Output Delay from the output frame boundary to the FPo1 rising edge	t _{FODR13}	46		66	ns	
4	CKo1 Output Clock Period	t _{CKP13}	106	122	148	ns	
5	CKo1 Output High Time	t _{CKH13}	46		87	ns	$C_L = 30 pF$
6	CKo1 Output Low Time	t _{CKL13}	46		66	ns	
7	CKo1 Output Rise/Fall Time	t _{rCK13} , t _{fCK13}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.



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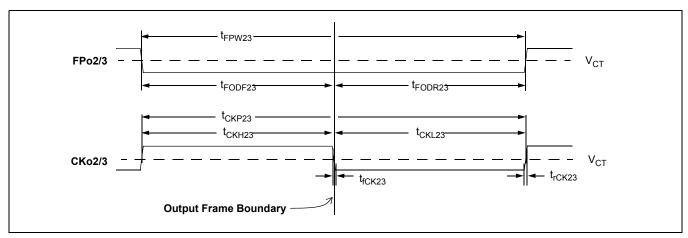


Figure 38 - FPo2 and CKo2 Timing Diagram

AC Electrical Characteristics[†] - FPo2/CKo2 and FPo3/CKo3 (16.384 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo2 Output Pulse Width	t _{FPW23}	56	61	66	ns	
2	FPo2 Output Delay from the FPo2 falling edge to the output frame boundary	t _{FODF23}	25		36	ns	$C_L = 30 pF$
3	FPo2 Output Delay from the output frame boundary to the FPo2 rising edge	t _{FODR23}	25		36	ns	
4	CKo2 Output Clock Period	t _{CKP23}	56	61	66	ns	
5	CKo2 Output High Time	t _{CKH23}	25		36	ns	$C_L = 30 pF$
6	CKo2 Output Low Time	t _{CKL23}	25		36	ns	
7	CKo2 Output Rise/Fall Time	t _{rCK23} , t _{fCK23}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - FPo2/CKo2 and FPo3/CKo3 (16.384 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Input Cycle to Cycle Variation

10 113	of input cycle to cycle variation						
	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo2 Output Pulse Width	t _{FPW23}	56	61	66	ns	
2	FPo2 Output Delay from the FPo2 falling edge to the output frame boundary	t _{FODF23}	25		36	ns	$C_L = 30 pF$
3	FPo2 Output Delay from the output frame boundary to the FPo2 rising edge	t _{FODR23}	25		36	ns	
4	CKo2 Output Clock Period	t _{CKP2}	47	61	76	ns	
5	CKo2 Output High Time	t _{CKH23}	17		43	ns	$C_L = 30 pF$
6	CKo2 Output Low Time	t _{CKL23}	17		43	ns	
7	CKo2Output Rise/Fall Time	t _{rCK23} , t _{fCK23}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.



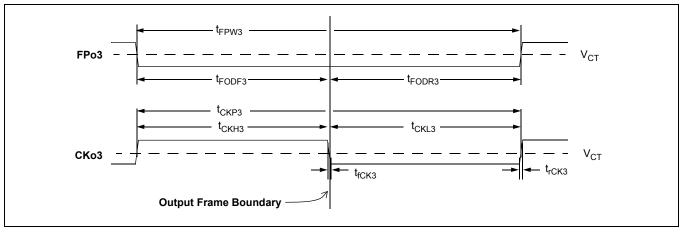


Figure 39 - FPo3 and CKo3 Timing Diagram

AC Electrical Characteristics[†] - FPo3/CKo3 (32.768 MHz) Timing for Divided Clock Mode and Multiplied Clock Mode with Less than 10 ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo3 Output Pulse Width	t _{FPW3}	27	30.5	34	ns	
2	FPo3 Output Delay from the FPo3 falling edge to the output frame boundary	t _{FODF3}	10		18	ns	C _L = 30 pF
3	FPo3 Output Delay from the output frame boundary to the FPo3 rising edge	t _{FODR3}	12		21	ns	
4	CKo3 Output Clock Period	t _{CKP3}	27	30.5	34	ns	
5	CKo3 Output High Time	t _{CKH3}	12		19	ns	$C_L = 30 pF$
6	CKo3 Output Low Time	t _{CKL3}	12		19	ns	
7	CKo3 Output Rise/Fall Time	t _{rCK3} , t _{fCK3}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics + - FPo3/CKo3 (32.768 MHz) Timing for Multiplied Clock Mode with More than 10 ns of Input Cycle to Cycle Variation

	Characteristic	Sym.	Min.	Typ.‡	Max.	Units	Notes
1	FPo3 Output Pulse Width	t _{FPW3}	27	30.5	34	ns	
2	FPo3 Output Delay from the FPo3 falling edge to the output frame boundary	t _{FODF3}	12		19	ns	C _L = 30 pF
3	FPo3 Output Delay from the output frame boundary to the FPo3 rising edge	t _{FODR3}	12		19	ns	
4	CKo3 Output Clock Period	t _{CKP3}	17	30.5	44	ns	
5	CKo3 Output High Time	t _{CKH3}	5		29	ns	$C_L = 30 pF$
6	CKo3 Output Low Time	t _{CKL3}	12		18	ns	
7	CKo3 Output Rise/Fall Time	t _{rCK3} , t _{fCK3}			5	ns	

[†] Characteristics are over recommended operating conditions unless otherwise stated.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

[‡] Typical figures are at 25°C, VDD_CORE at 1.8 V and VDD_IO at 3.3 V and are for design aid only: not guaranteed and not subject to production testing.

AC Electrical Characteristics[†] - Divided Clock Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns
3	CKo0 to CKo3 (16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-2	2	ns

[†] Characteristics are over recommended operating conditions unless otherwise stated.

AC Electrical Characteristics[†] - Multiplied Clock Mode Output Timing

	Characteristic	Sym.	Min.	Max.	Units
1	CKo0 to CKo1 (8.192 MHz) delay	t _{C1D}	-1	2	ns
2	CKo0 to CKo2 (16.384 MHz) delay	t _{C2D}	-1	3	ns
3	CKo0 to CKo3 (32.768 MHz/16.384 MHz/8.192 MHz/4.096 MHz) delay	t _{C3D}	-1	3	ns

[†] Characteristics are over recommended operating conditions unless otherwise stated.

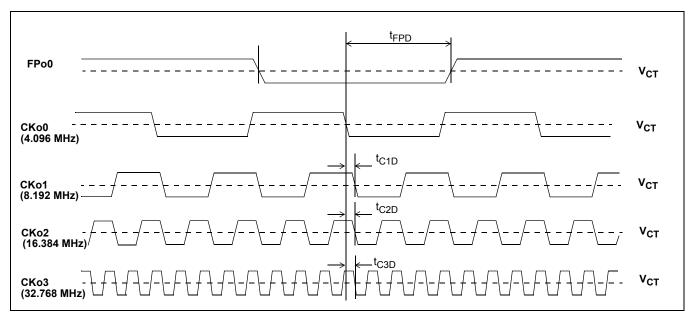


Figure 40 - Output Timing (ST-BUS Format)

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